

## SCHOOL OF ELECTRONICS ENGINEERING

# M. Tech VLSI Design

## (M.Tech MVD)

Curriculum

(2021-2022 admitted students)

## VISION STATEMENT OF VELLORE INSTITUTE OF TECHNOLOGY

Transforming life through excellence in education and research. MISSION STATEMENT OF VELLORE INSTITUTE OF TECHNOLOGY

**World class Education**: Excellence in education, grounded in ethics and critical thinking, for improvement of life.

**Cutting edge Research**: An innovation ecosystem to extend knowledge and solve critical problems.

**Impactful People**: Happy, accountable, caring and effective workforce and students.

**Rewarding Co-creations**: Active collaboration with national & internationalindustries & universities for productivity and economic development.

**Service to Society**: Service to the region and world through knowledge and compassion.

## VISION STATEMENT OF THE SCHOOL OF ELECTRONICS ENGINEERING

To be a leader by imparting in-depth knowledge in Electronics Engineering, nurturing engineers, technologists and researchers of highest competence, who would engage in sustainable development to cater the global needs of industry and society.

## MISSION STATEMENT OF THE SCHOOL OF ELECTRONICS ENGINEERING

- Create and maintain an environment to excel in teaching, learning and applied research in the fields of electronics, communication engineering and allied disciplines which pioneer for sustainable growth.
- Equip our students with necessary knowledge and skills which enable them to be lifelong learners to solve practical problems and to improve the quality of human life.

## M. Tech. VLSI Design

## **PROGRAMME EDUCATIONAL OBJECTIVES (PEOs)**

1. Graduates will be engineering practitioners and leaders, who would help solve industry's technological problems.

2. Graduates will be engineering professionals, innovators or entrepreneurs engaged in technology development, technology deployment, or engineering system implementation in industry.

3. Graduates will function in their profession with social awareness and responsibility.

4. Graduates will interact with their peers in other disciplines in industry and society and contribute to the economic growth of the country.

5. Graduates will be successful in pursuing higher studies in engineering or management.

6. Graduates will pursue career paths in teaching or research.

## M. Tech VLSI Design

## **PROGRAMME OUTCOMES (POs)**

PO\_01: Having an ability to apply mathematics and science in engineering applications.

PO\_02: Having an ability to design a component or a product applying all the relevant standards and with realistic constraints, including public health, safety, culture, society and environment

PO\_03: Having an ability to design and conduct experiments, as well as to analyse and interpret data, and synthesis of information

PO\_04: Having an ability to use techniques, skills, resources and modern engineering and IT tools necessary for engineering practice

PO\_05: Having problem solving ability- to assess social issues (societal, health, safety, legal and cultural) and engineering problems

PO\_06: Having adaptive thinking and adaptability in relation to environmental context and sustainable development

PO\_07: Having a clear understanding of professional and ethical

responsibility

PO\_08: Having a good cognitive load management skills related to project management and finance

## **PROGRAMME SPECIFIC OUTCOMES (PSOs)**

On completion of M. Tech. (VLSI Design) programme, graduates will be able to

**PSO1:** Apply advanced concepts in Physics of semiconductor devices to design VLSI Systems.

**PSO2:** Design ASIC and FPGA based systems using industry standard tools.

**PSO3:** Solve research gaps and provide solutions to socio-economic, and environmental problems.

## Category-wise Credit distribution

Category	Credits
University core (UC)	27
Programme core (PC)	19
Programme elective (PE)	18
University elective (UE)	6
Bridge course (BC)	
Total credits	70

## **Detailed curriculum**

(as given in the student curriculum view – in the order of UC, UE, PC and PE). Courses need not be listed under UE.

## **University Core - 27 Credits**

<b>S.</b>	Course Code	Course Title	L	Τ	P	J	C
No							
1.	MAT5009	Advanced Computer	2	2	0	0	3
		Arithmetic					
2.	ENG5001 and	Technical English I and	{0	0	2	0	2
	ENG5002	Technical English II	0	0	2	0}	
	(or) EFL5097	(or) Foreign Language	2	0	0	0	
3.	STS5001	Soft Skills	0	0	0	0	1
4.	STS5002	Soft Skills	0	0	0	0	1
5.	SET5001	SET Project-I	0	0	0	0	2
6.	SET5002	SET Project-II	0	0	0	0	2
7.	ECE6099	Master's Thesis	0	0	0	0	16

## **University Elective – 6 Credits**

S.No	Course Title		Τ	Ρ	J	C
1	University Elective <sup>#</sup>	-	-	-	-	6

# All courses offered by other M.Tech Programmes / PE of M.Tech (VLSI Design)

## **Programme Core – 19 Credits**

S. Io	Course Code	<b>Course Title</b>	L	Т	Р	J	С
1	ECE5014	ASIC Design	3	0	2	0	4
2	ECE5015	Digital IC Design	3	0	0	4	4
3	ECE5016	Analog IC Design	3	0	2	0	4
4	ECE5017	Digital Design with FPGA	2	0	2	4	4
5	ECE5018	Physics of VLSI Devices	3	0	0	0	3

## **Programme Electives - 18 Credits**

S. No	Course Code	<b>Course Title</b>	L	Т	Р	J	C
1	ECE5019	Computer Aided Design for VLSI		0	0	0	3
2	ECE5020	DSP Architectures	2	0	0	4	3
3	ECE5022	VLSI Digital Signal Processing	3	0	0	0	3
4	ECE5023	Memory Design and Testing	3	0	0	0	3
5	ECE5024	IC Technology	3	0	0	0	3
6	ECE5025	System-on-Chip Design	3	0	0	0	3
7	ECE5026	System Design with FPGA	2	0	0	4	3
8	ECE5027	Advanced Computer Architecture	3	0	0	0	3
9	ECE5028	Micro Sensors and Interface Electronics	2	0	0	4	3
10	ECE5029	VLSI Testing and Testability	3	0	0	0	3
11	ECE5030	Scripting languages for VLSI design automation	2	0	2	0	3
12	ECE6024	VLSI Verification Methodologies	2	0	0	4	3
13	ECE6025	Low Power IC Design	2	0	0	4	3
14	ECE6026	Mixed Signal IC Design	2	0	0	4	3
15	ECE6027	RFIC Design	2	0	0	4	3
16	ECE6028	Nanoscale Devices and Circuit Design	2	0	0	4	3

**Syllabus** 

Course Code	Course Title	L T P J C
MAT5009	ADVANCED COMPUTER ARITHMETIC	$\begin{array}{c ccccccccccccccccccccccccccccccccccc$
Pre-requisite	None	Syllabus
-		version
<b>Course Objectives</b>		
The course aimed t		
	ne representation of the numbers using redundant and residue num	•
	arious integer arithmetic algorithms, FFT and modular arithmetic	
	floating-point arithmetic algorithms and its impacts on resulting e	error and its
corrective n		
	ORDIC algorithm for calculating various functions of common inter- e implementation aspects of high throughput, low power and fault	
arithmetic c		loierain
	incuits.	
Expected Course	Outcome:	
The students will b		
	and represent the numbers using redundant and residue number s	ystem.
	and apply various integer arithmetic algorithms.	-
	and apply various FFT and modular arithmetic algorithms.	
4. Understand	floating-point arithmetic algorithms, apply it, analyse the impacts	s of resulting
	s corrective methods.	
	and apply CORDIC algorithm for calculating various functions o	f common
interest.		1 1
	the implementation aspects of high throughput, low power and fa	ult tolerant
arithmetic c	circuits.	
Module:1 Intro	duction to computer Arithmetic	5 hours
	s and arithmetic. Redundant number systems. Residue number systems.	
	er Arithmetic	7 hours
Addition and Sub	straction. Multiplication. Division. Roots. Greatest Common E	Division. Base
Conversion: Quadr	atic Algorithms, Sub quadratic Algorithms.	
<b></b>		
	and Modular Arithmetic	6 hours
Kepresentation: C	lassical Representation, Montgomery's Form, Residue Number S	
	ns, Link with Polynomials. Addition and Subtration. Multiplica	
vs LSB Algorithm	•	
vs LSB Algorithm Algorithm, Montg	gomery's Multiplication, McLaughlin's Algorithm, Special	Moduli, Fast
vs LSB Algorithm Algorithm, Montg Multiplication Ove	•	Moduli, Fast
vs LSB Algorithm Algorithm, Montg	gomery's Multiplication, McLaughlin's Algorithm, Special	Moduli, Fast
vs LSB Algorithm Algorithm, Montg Multiplication Ove Theorem.	gomery's Multiplication, McLaughlin's Algorithm, Special er GF (2)[x]. Division and Inversion, Exponentiation, Chine	Moduli, Fast
vs LSB Algorithm Algorithm, Montg Multiplication Ove Theorem. Module:4 Float	gomery's Multiplication, McLaughlin's Algorithm, Special er GF (2)[x]. Division and Inversion, Exponentiation, Chine ing Point Arithmetic	Moduli, Fast se Remainder 7 hours
vs LSB Algorithm Algorithm, Montg Multiplication Ove Theorem. Module:4 Float	gomery's Multiplication, McLaughlin's Algorithm, Special er GF (2)[x]. Division and Inversion, Exponentiation, Chine ing Point Arithmetic resentation. Floating point operation. Errors and Error control	Moduli, Fast se Remainder 7 hours
vs LSB Algorithm Algorithm, Montg Multiplication Ove Theorem. Module:4 Floati Floating point rep	gomery's Multiplication, McLaughlin's Algorithm, Special er GF (2)[x]. Division and Inversion, Exponentiation, Chine ing Point Arithmetic resentation. Floating point operation. Errors and Error control	Moduli, Fast se Remainder 7 hours
vs LSB Algorithm Algorithm, Montg Multiplication Ove Theorem. Module:4 Floati Floating point rep certifiable arithmet Module:5 Funct	gomery's Multiplication, McLaughlin's Algorithm, Special er GF (2)[x]. Division and Inversion, Exponentiation, Chine ing Point Arithmetic resentation. Floating point operation. Errors and Error control ic.	Moduli, Fast se Remainder 7 hours I. Precise and 7 hours
vs LSB Algorithm Algorithm, Montg Multiplication Ove Theorem. Module:4 Floati Floating point rep certifiable arithmet Module:5 Funct	gomery's Multiplication, McLaughlin's Algorithm, Special er GF (2)[x]. Division and Inversion, Exponentiation, Chine ing Point Arithmetic resentation. Floating point operation. Errors and Error control ic.	Moduli, Fast se Remainder 7 hours I. Precise and 7 hours
vs LSB Algorithm Algorithm, Montg Multiplication Ove Theorem. Module:4 Floati Floating point rep certifiable arithmet Module:5 Funct	gomery's Multiplication, McLaughlin's Algorithm, Special er GF (2)[x]. Division and Inversion, Exponentiation, Chine ing Point Arithmetic resentation. Floating point operation. Errors and Error control ic. ic. ion Evaluation fethods. The CORDIC Algorithms . Variations in Function Evaluation	Moduli, Fast se Remainder 7 hours I. Precise and 7 hours
vs LSB Algorithm Algorithm, Montg Multiplication Ove Theorem. Module:4 Floati Floating point rep certifiable arithmet Module:5 Funct Square-Rooting M	gomery's Multiplication, McLaughlin's Algorithm, Special er GF (2)[x]. Division and Inversion, Exponentiation, Chine ing Point Arithmetic resentation. Floating point operation. Errors and Error control ic. ic. ion Evaluation fethods. The CORDIC Algorithms . Variations in Function Evaluation	Moduli, Fast se Remainder 7 hours I. Precise and 7 hours

Hig	gh throug	hput arithmetic, Low powe	er arithmetic, faul	t tolerant	arithmetic	
Mo	dule:7	Error Analysis				6 hours
Abs	solute V	ersus Relative Error, Sig	nificant Digits.	Uncertain	nty in Data. Chop	ping off and
Roi	unding of	ff. Truncation Error. Loss of	of Significance.			
	110					
Mo	dule:8	Contemporary issues:				2 hours
				Tota	al Lecture hours:	45 hours
Tey	xt Books					
1.		z Parhami, "Computer Arit sity Press 2015.	hmetic: Algorith	ms and H	ardware Design", (2	/e) Oxford
2.		1 P Brent and Paul Zim sity Press 2010.	merman, "Mode	rn Comp	outer Arithmetic", (	Cambridge
Ref	ference l	Books				
1.		Vladutiu, "Computer A er 2012.	arithmetic: Algo	rithms a	nd Hardware Imp	lementation",
2.		W. Kulisch "Computer Ariations", De Gruyter; 2 editions		lity: Theo	ory, Implementation,	, and
Mo	de of Ev	valuation: Continuous Asse	essment Test –I (	CAT-I),	Continuous Assess	ment Test –II
(CA	AT-II), S	eminar / Challenging Assig	gnments / Compl	etion of N	MOOC / Innovative	
		for industrial problems, Fin	17-02-2016	est (FAI)	).	
		led by Board of Studies y Academic Council	No. 47	Date	05-10-2017	

Course code	Course title	L T P J C
ENG5001	Fundamentals of Communication Skills	L         T         P         J         C           0         0         2         0         1
Pre-requisite	Not cleared EPT (English Proficiency Test)	Syllabus version
		1.0
Course Objectives		1 337 '4'
	rs learn basic communication skills - Listening, Speaking, Readiapply effective communication in social and academic context	ng and Writing
3. To make student	s comprehend complex English language through listening and 1	reading
		6
Expected Course	Outcome:	
	ening and comprehending skills of the learners	
	skills to express their thoughts freely and fluently	
	For effective reading	
-	al correct sentences in general and academic writing	
0	al writing skills like writing instructions, transcoding etc.,	
· · · · · · · · · · · · · · · · · · ·	<u> </u>	
Module:1 Listen	ing	8 hours
Understanding Cor		0 110015
Listening to Speech		
Listening for Speci		
Module:2 Speak		4 hours
Exchanging Inform		inours
	es, Events and Quantity	
Module:3 Read		6 hours
Identifying Information	<u> </u>	0 110 011 5
Inferring Meaning		
Interpreting text		
Module:4 Writin	ng. Sentence	8hours
Basic Sentence Str		onours
Connectives		
Transformation of	Sentences	
Synthesis of Senter		
	ng: Discourse	4hours
Instructions	-0. =	inouib
Paragraph		
Transcoding		
0		
		30 hours
	Total Lecture hours:	
Text Book(s)		1
1. Redston, Chi	ris, Theresa Clementson, and Gillie Cunningham. Face2	face Upper
· · ·	tudent's Book. 2013, Cambridge University Press.	~rr~
Reference Books		
	.Stepping Stones: A guided approach to writing sentences and F	aragraphs
	on), 2012, Library of Congress.	
· ·	hitcomb & Leslie E Whitcomb, Effective Interpersonal and Team	1
	accome a Leone L macomo, Encenve interpersonal and reall	•

	Communication Skills for Enginee		•		•			
3.	ArunPatil, Henk Eijkman & Ena Bhattacharya, New Media Communication Skills for Engineers and IT Professionals, 2012, IGI Global, Hershey PA.							
4	Judi Brownell, Listening: Attitudes, Principles and Skills, 2016, 5 <sup>th</sup> Edition, Routledge:USA							
	John Langan, Ten Steps to Improving College Reading Skills, 2014, 6 <sup>th</sup> Edition, Townsend							
	Press:USA	vilig College Rea	unig Skin	5, 2014, 0 Eul	uon, rownsend			
	Redston, Chris, Theresa Clements	on and Gillie Cu	nningham	Face2face Upr	er Intermediate			
0.	Teacher's Book. 2013, Cambridge		iiiiiigiiaiiii.	Tueeziuee opp	or interinediate			
	Authors, book title, year of publica	tion, edition num	ber, press,	place				
Mod	le of Evaluation: CAT / Assignmen	t / Quiz / FAT / P	roject / Se	minar				
List	of Challenging Experiments (Ind	licative)						
1.	Familiarizing students to adjective	es through brainst	orming adj	ectives with	2 hours			
	all letters of the English alphabet a	Ũ	o add an ao	ljective that				
	starts with the first letter of their n	ame as a prefix.						
2.	Making students identify their pee	r who lock Doce	<u>Clarity and</u>	l Volume	4 hours			
2.	during presentation and respond u			i volume	4 110013			
	during presentation and respond u	sing 5 ymoors.						
3.	Using Picture as a tool to enhance learners speaking and writing skills							
4.	Using Music and Songs as tools t	o enhance pronun	ciation in	the target	2 hours			
	language / Activities through VIT	-		e				
_								
5.	Making students upload their Self				4 hours			
6.	Brainstorming idiomatic expression	0	em use the	ose in to their	4 hours			
7	writings and day to day conversati		• ,•	1	4.1			
7.	Making students Narrate events by				4 hours			
8	add flavor to their language / Acti			•	4 hours			
0	Identifying the root cause of stage make their presentation better	iear in learners a	na proviai	lig remedies to	4 110018			
9	Identifying common Spelling & S	entence errors in	Letter Wri	ting and other	2 hours			
	day to day conversations							
10.	Discussing FAQ's in interviews w				2 hours			
	better insight in to interviews / Ac	tivities through V	IT Comm	unity Radio				
	1		Total I	Practical Hours	30 hours			
Mod	le of evaluation: Online Quizzes, Pr	resentation. Role						
	i Project	· · · · · ·	L J/		0			
	ommended by Board of Studies	22-07-2017						
	roved by Academic Council	No. 46	Date	24-8-2017				

<b>Course Code</b>	•	Course Title	L T P J C
ENG5002		Professional and Communication Skills	0 0 2 0 1
<b>Pre-requisite</b>	)	ENG5001	Syllabus
-			version
			1.1
Course Obje	ctives	:	
		ts to develop effective Language and Communication Skills	
2. To enhance	e stud	ents' Personal and Professional skills	
3. To equip th	ie stuc	lents to create an active digital footprint	
E 4 1 C			
Expected Con			
-	-	ersonal communication skills	
		m solving and negotiation skills and mechanics of writing research reports	
		public speaking and presentation skills	
		red skills and excel in a professional environment	
J. Apply the	acqui		
Module:1	Pers	onal Interaction	2hours
		f- one's career goals	
C			
Activity: SW	OT A	nalysis	
Madular2	Trator	manganal Interaction	2 h anna
Module:2		rpersonal Interaction	2 hours
Interpersonal	Comr	nunication with the team leader and colleagues at the workplace	
Activity: Role	e Play	s/Mime/Skit	
-			
Module:3		al Interaction	2 hours
Use of Social	Medi	a, Social Networking, gender challenges	
Activity: Crea	ating I	LinkedIn profile, blogs	
Module:4	Résu	umé Writing	4 hours
Identifying jo	b requ	irement and key skills	
Activity: Prep	oare ar	n Electronic Résumé	
Module:5	Inte	rview Skills	4 hours
Placement/Jol	b Inter	rview, Group Discussions	
Activity: Moc	ek Inte	erview and mock group discussion	
-		· · ·	
Module:6	Repo	ort Writing	4 hours
Languaga and	Maal	panios of Writing	
Language and	i ivieci	hanics of Writing	
Activity: Writ	ting a	Report	
	<u> </u>		<b>A1</b>
Module:7		y Skills: Note making	2hours
Summarizing		•	
Activity: Abst	tract,	Executive Summary, Synopsis	

Module:8		Interpreting skills	2 hours
	*	in tables and graphs	
Acti	vity: Trar	nscoding	
Mod	lule:9	Presentation Skills	4 hours
Oral	Presenta	tion using Digital Tools	
Acti	vity: Oral	l presentation on the given topic using appropriate non-verbal cues	
	•		
Mod	lule:10	Problem Solving Skills	4 hours
Prob	lem Solv	ing & Conflict Resolution	
		0	
Acti	vity: Case	e Analysis of a Challenging Scenario Total Lecture hours	: 30hours
		1 otal Lecture nours	: Sonours
Tex	t Book(s)		
	-	gar Nitin and Mamta Bhatnagar, Communicative English For	
D	0	ers And Professionals, 2010, Dorling Kindersley (India) Pvt. Ltd.	
Refe	erence Bo	boks kman and Christopher Turk, Effective Writing: Improving Scientific,	Technical and
		s Communication, 2015, Routledge	i cennicar and
		Bairaktarova and Michele Eodice, Creative Ways of Knowing in En r International Publishing	gineering, 2017,
	Springe	i international Fuolisining	
		A Whitcomb & Leslie E Whitcomb, Effective Interperso	
	Commu	inication Skills for Engineers, 2013, John Wiley & Sons, Inc., Hobok	en: New Jersey.
	ArunPa	til, Henk Eijkman &Ena Bhattacharya, New Media Communic	ation Skills for
		ers and IT Professionals,2012, IGI Global, Hershey PA.	
M			
MOC	le of Eval	uation: CAT / Assignment / Quiz / FAT / Project / Seminar	
		enging Experiments (Indicative)	
1.	SWOT weakne	Analysis – Focus specially on describing two strengths and two	2 hours
	weakile	5555	
2.	Role Pla	ays/Mime/Skit Workplace Situations	4 hours
3.	Use of S	Social Media – Create a LinkedIn Profile and also write a page or	2 hours
		areas of interest	
4.	Prenare	an Electronic Résumé and upload the same in vimeo	2 hours
5.		liscussion on latest topics	4 hours
6 7	-	Writing – Real-time reports an Abstract, Executive Summary on short scientific or research	2 hours 4 hours
,	articles	an restract, Executive Summary on short scientific of research	r nouis
8		ding – Interpret the given graph, chart or diagram	2 hours

9	4 hours							
10	10 Problem Solving Case Analysis of a Challenging Scenario							
	Total Laboratory Hours							
Mod	le of evaluation: : Online Quizzes,	Presentation, Role	play, Gro	up Discussions,	, Assignments,			
Mini	i Project							
Reco	Recommended by Board of Studies 22-07-2017							
App	roved by Academic Council	No. 47	Date	05-10-2017				

Course Code	Course Title	L T P J C
GER5001	Deutsch für Anfänger	L         I         P         J         C           2         0         0         0         2
Pre-requisite	Deutsch für Amanger           NIL	Syllabus
rre-requisite	NIL	version
		version v.1
Course Objective	c•	V.1
v	tudents the necessary background to:	
-	lents to read and communicate in German in their day to day life	
2. become inc		
	understand the usage of grammar in the German Language.	
5. make them	understand the usage of grammar in the German Language.	
Expected Course	Outcome:	
The students will b		
	of German language in their day to day life.	
	onjugation of different forms of regular/irregular verbs.	
	ale to identify the gender of the Nouns and apply articles appropri	atelv.
	n language skill in writing corresponding letters, E-Mails etc.	
	of translating passages from English-German and vice versa and	Го frame
	based on given situations.	
1 1 0	<u> </u>	
Module:1		3 hours
Einleitung, Begrü	ssungsformen, Landeskunde, Alphabet, Personalpronomen, Verl	
0 0	-fragen, Aussagesätze, Nomen – Singular und Plural	<b>J</b> ,
Lernziel:	indeni, massagesaule, moment singular and matar	
	ändnis von Deutsch, Genus- Artikelwörter	
Elementares vers	andins von Deutsen, Genus Antikerworten	
Module:2		3 hours
	erben (regelmässig /unregelmässig) die Monate, die Wochentage,	
	en, Artikel, Zahlen (Hundert bis eine Million), Ja-/Nein- Frage, In	•
Sie		-F
Lernziel :		
Sätze schreiben, ül	ber Hobbys erzählen, über Berufe sprechen usw.	
Module:3		4 hours
	n, Negation, Kasus- AkkusatitvundDativ (bestimmter, unbesti	
1	, Modalverben, Adjektive, Uhrzeit, Präpositionen, Mahlzeiten,	,,
Getränke	,,,,,,,,	,
Lernziel :		
	erben, Verwendung von Artikel, über Länder und Sprachen spred	hen jiher eine
Wohnung beschreit		
tt onnung besehlte		
Module:4		6 hours
	Deutsch – Englisch / Englisch – Deutsch)	5 110415
Lernziel :	Jeutsen – Englisen / Englisen – Deutsen)	
	toohotz Ühung	
Grammatik – Wor	ischatz – Obulig	
Modula:5		5 k
Module:5		5 hours
· · · · · · · · · · · · · · · · · · ·	lindmap machen, Korrespondenz- Briefe, Postkarten, E-Mail	

Lernziel :	
Wortschatzbildung und aktiver Sprach gebrauch	
	1
Module:6 .	3 hours
Aufsätze : Meine Universität, Das Essen, mein Freund oder meine Freundin, meine Fa Deutschland usw	amilie, ein Fest in
Module:7	4 hours
Dialoge:	
a) Gespräche mit Familienmitgliedern, Am Bahnhof,	
b) Gespräche beim Einkaufen ; in einem Supermarkt ; in einer Buchha	indlung;
c) in einem Hotel - an der Rezeption ;ein Termin beim Arzt.	
Treffen im Cafe	
Module:8	2 hours
Guest Lectures/Native Speakers / Feinheiten der deutschen Sprache, Ba deutschsprachigen Länder	
Total Lecture	e hours: 30 hours
Text Book(s)	
1. Studio d A1 Deutsch als Fremdsprache, Hermann Funk, Chr Demme : 2012	ristina Kuhn, Silke
Reference Books	
NCICI CIICE DUUKS	
1 Netzwerk Deutsch als Fremdsprache A1, Stefanie Dengler, Paul Rusch	n, Helen Schmtiz, Tanja
1 Netzwerk Deutsch als Fremdsprache A1, Stefanie Dengler, Paul Rusch Sieber, 2013	n, Helen Schmtiz, Tanja
<ol> <li>Netzwerk Deutsch als Fremdsprache A1, Stefanie Dengler, Paul Rusch Sieber, 2013</li> <li>Lagune ,Hartmut Aufderstrasse, Jutta Müller, Thomas Storz, 2012.</li> </ol>	
<ol> <li>Netzwerk Deutsch als Fremdsprache A1, Stefanie Dengler, Paul Rusch Sieber, 2013</li> <li>Lagune ,Hartmut Aufderstrasse, Jutta Müller, Thomas Storz, 2012.</li> <li>Deutsche SprachlehrefürAUsländer, Heinz Griesbach, Dora Schulz, 20</li> </ol>	011
<ol> <li>Netzwerk Deutsch als Fremdsprache A1, Stefanie Dengler, Paul Rusch Sieber, 2013</li> <li>Lagune ,Hartmut Aufderstrasse, Jutta Müller, Thomas Storz, 2012.</li> <li>Deutsche SprachlehrefürAUsländer, Heinz Griesbach, Dora Schulz, 20</li> </ol>	011
<ol> <li>Netzwerk Deutsch als Fremdsprache A1, Stefanie Dengler, Paul Rusch Sieber, 2013</li> <li>Lagune ,Hartmut Aufderstrasse, Jutta Müller, Thomas Storz, 2012.</li> <li>Deutsche SprachlehrefürAUsländer, Heinz Griesbach, Dora Schulz, 20</li> <li>ThemenAktuell 1, HartmurtAufderstrasse, Heiko Bock, MechthildGer</li> </ol>	011
<ol> <li>Netzwerk Deutsch als Fremdsprache A1, Stefanie Dengler, Paul Rusch Sieber, 2013</li> <li>Lagune ,Hartmut Aufderstrasse, Jutta Müller, Thomas Storz, 2012.</li> <li>Deutsche SprachlehrefürAUsländer, Heinz Griesbach, Dora Schulz, 20</li> <li>ThemenAktuell 1, HartmurtAufderstrasse, Heiko Bock, MechthildGer Helmut Müller, 2010</li> </ol>	011
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<ol> <li>Netzwerk Deutsch als Fremdsprache A1, Stefanie Dengler, Paul Rusch Sieber, 2013</li> <li>Lagune ,Hartmut Aufderstrasse, Jutta Müller, Thomas Storz, 2012.</li> <li>Deutsche SprachlehrefürAUsländer, Heinz Griesbach, Dora Schulz, 20</li> <li>ThemenAktuell 1, HartmurtAufderstrasse, Heiko Bock, MechthildGer Helmut Müller, 2010</li> <li>www.goethe.de wirtschaftsdeutsch.de</li> </ol>	011
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<ol> <li>Netzwerk Deutsch als Fremdsprache A1, Stefanie Dengler, Paul Rusch Sieber, 2013</li> <li>Lagune ,Hartmut Aufderstrasse, Jutta Müller, Thomas Storz, 2012.</li> <li>Deutsche SprachlehrefürAUsländer, Heinz Griesbach, Dora Schulz, 20</li> <li>ThemenAktuell 1, HartmurtAufderstrasse, Heiko Bock, MechthildGer Helmut Müller, 2010</li> <li>www.goethe.de wirtschaftsdeutsch.de hueber.de klett-sprachen.de</li> </ol>	011

<ul> <li>sports/hobbies, classroom and family).</li> <li>2. achieve proficiency in French culture oriented view point.</li> </ul> Expected Course Outcome: The students will be able to <ol> <li>remember the daily life communicative situations via personal pronouns, emphatic pronouns, salutations, negations, interrogations etc.</li> <li>create communicative skill effectively in French language via regular / irregular via demonstrate comprehension of the spoken / written language in translating simple sentences. understand and demonstrate the comprehension of some particular new range of u written materials.</li></ol>	Syllabus versior 1.( including orkplace
Course Objectives:         The course gives students the necessary background to:         1. demonstrate competence in reading, writing, and speaking basic French, knowledge of vocabulary (related to profession, emotions, food, w sports/hobbies, classroom and family).         2. achieve proficiency in French culture oriented view point.         Expected Course Outcome:         The students will be able to         1. remember the daily life communicative situations via personal pronouns, emphatic pronouns, salutations, negations, interrogations etc.         2. create communicative skill effectively in French language via regular / irregular v.         3. demonstrate comprehension of the spoken / written language in translating simple sentences.         4. understand and demonstrate the comprehension of some particular new range of u written materials.	version 1.( including orkplace
<ul> <li>The course gives students the necessary background to: <ol> <li>demonstrate competence in reading, writing, and speaking basic French, knowledge of vocabulary (related to profession, emotions, food, w sports/hobbies, classroom and family).</li> <li>achieve proficiency in French culture oriented view point.</li> </ol> </li> <li>Expected Course Outcome: The students will be able to <ol> <li>remember the daily life communicative situations via personal pronouns, emphatic pronouns, salutations, negations, interrogations etc. create communicative skill effectively in French language via regular / irregular via. demonstrate comprehension of the spoken / written language in translating simple sentences. understand and demonstrate the comprehension of some particular new range of u written materials.</li></ol></li></ul>	version 1.( including orkplace
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<ul> <li>Expected Course Outcome:</li> <li>The students will be able to <ol> <li>remember the daily life communicative situations via personal pronouns, emphatic pronouns, salutations, negations, interrogations etc.</li> <li>create communicative skill effectively in French language via regular / irregular via demonstrate comprehension of the spoken / written language in translating simple sentences.</li> <li>understand and demonstrate the comprehension of some particular new range of u written materials.</li> </ol> </li> </ul>	erbs.
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<ol> <li>The students will be able to         <ol> <li>remember the daily life communicative situations via personal pronouns, emphatic pronouns, salutations, negations, interrogations etc.</li> <li>create communicative skill effectively in French language via regular / irregular vi demonstrate comprehension of the spoken / written language in translating simple sentences.</li> <li>understand and demonstrate the comprehension of some particular new range of u written materials.</li> </ol> </li> </ol>	erbs.
<ol> <li>remember the daily life communicative situations via personal pronouns, emphatic pronouns, salutations, negations, interrogations etc.</li> <li>create communicative skill effectively in French language via regular / irregular via demonstrate comprehension of the spoken / written language in translating simple sentences.</li> <li>understand and demonstrate the comprehension of some particular new range of u written materials.</li> </ol>	erbs.
<ul> <li>pronouns, salutations, negations, interrogations etc.</li> <li>create communicative skill effectively in French language via regular / irregular via demonstrate comprehension of the spoken / written language in translating simple sentences.</li> <li>understand and demonstrate the comprehension of some particular new range of u written materials.</li> </ul>	erbs.
<ol> <li>create communicative skill effectively in French language via regular / irregular v.</li> <li>demonstrate comprehension of the spoken / written language in translating simple sentences.</li> <li>understand and demonstrate the comprehension of some particular new range of u written materials.</li> </ol>	
<ol> <li>demonstrate comprehension of the spoken / written language in translating simple sentences.</li> <li>understand and demonstrate the comprehension of some particular new range of u written materials.</li> </ol>	
<ul><li>sentences.</li><li>understand and demonstrate the comprehension of some particular new range of u written materials.</li></ul>	
4. understand and demonstrate the comprehension of some particular new range of u written materials.	
written materials.	
	nseen
<b>5</b> demonstrate a strategical metric d'une s <b>f</b> (the Energy three strategical	1. J
5. demonstrate a clear understanding of the French culture through the language stud	nea.
Module:1 Saluer, Se présenter, Etablir des contacts	3 hours
Les Salutations, Les nombres (1-100), Les jours de la semaine, Les mois de l'année, Les	
Sujets, Les Pronoms Toniques, La conjugaison des verbes réguliers, La conjugaison de	es verbes
irréguliers- avoir / être / aller / venir / faire etc.	
Module:2 Présenter quelqu'un, Chercher un(e) correspondant(e),	3 hours
Demander des nouvelles d'une personne.	J Hour
La conjugaison des verbes Pronominaux, La	Négation
L'interrogation avec 'Est-ce que ou sans Est-ce que'.	U
Module:3 Situer un objet ou un lieu, Poser des questions	4 hours
L'article (défini/ indéfini), Les prépositions (à/en/au/aux/sur/dans/avec etc.), L'article of	
Les heures en français, La Nationalité du Pays, L'adjectif (La Couleur, l'adjectif	
	-
1 adjecui demonstratii/ i adjecui interrogatii (quel/quelles/quelle/quelles), L'ad	
l'adjectif démonstratif/ l'adjectif interrogatif (quel/quelles/quelle/quelles), L'ac adjectifs avec le nom, L'interrogation avec Comment/ Combien / Où etc.,	
adjectif demonstratif/ l'adjectif interrogatif (quel/quelles/quelle/quelles), L'adjectifs avec le nom, L'interrogation avec Comment/ Combien / Où etc.,	
adjectifs avec le nom, L'interrogation avec Comment/ Combien / Où etc.,	
adjectifs avec le nom, L'interrogation avec Comment/ Combien / Où etc.,         Module:4       Faire des achats, Comprendre un texte court, Demander et	6 hours
adjectifs avec le nom, L'interrogation avec Comment/ Combien / Où etc.,         Module:4       Faire des achats, Comprendre un texte court, Demander et indiquer le chemin.	
adjectifs avec le nom, L'interrogation avec Comment/ Combien / Où etc.,         Module:4       Faire des achats, Comprendre un texte court, Demander et	
adjectifs avec le nom, L'interrogation avec Comment/ Combien / Où etc.,         Module:4       Faire des achats, Comprendre un texte court, Demander et indiquer le chemin.         La traduction simple :(français-anglais / anglais –français)	6 hours
adjectifs avec le nom, L'interrogation avec Comment/ Combien / Où etc.,         Module:4       Faire des achats, Comprendre un texte court, Demander et indiquer le chemin.         La traduction simple :(français-anglais / anglais –français)         Module:5       Trouver les questions, Répondre aux questions générales en	
adjectifs avec le nom, L'interrogation avec Comment/ Combien / Où etc.,         Module:4       Faire des achats, Comprendre un texte court, Demander et indiquer le chemin.         La traduction simple :(français-anglais / anglais –français)	6 hours 5 hours

Mod	lule:6	Comment ecrire un pass	age			3 hours
Déci	rivez :					
La F	famille /	/La Maison, /L'université /I	Les Loisirs/ La Vie	e quotidier	ne etc.	
		Γ				
	lule:7	Comment ecrire un dialo	ogue			4 hours
	ogue:					
	/	erver un billet de train				
		e deux amis qui se rencontr				
-	/	ni les membres de la famille	e			
£	g) Ent	re le client et le médecin				
		T				
Mod	lule:8	Invited Talk: Native spe	eakers			2 hours
				TatalI	atura harras	30 hours
				I otal Lo	ecture hours:	30 nours
Torr	t Book(	a)				
		s) , Méthode de français, J. Gi	irardet I Pécheur	Publisher	CI E Internatio	nal Paris 2010
		, Cahier d'exercices, J. Gira	,	,		
	erence		indet, 5. i cenedi, i			ai, 1 ans 2010.
		EXIONS 1, Méthode de fra	ncais. Régine Mé	rieux. Yve	s Loiseau.Les É	Editions Didier.
	2004.			,		,
	20011					
2	CONN	EXIONS 1, Le cahier d'ex	ercices, Régine M	érieux, Yv	es Loiseau, Les	s Éditions
	Didier,			,	,	
	,					
3	ALTE	R EGO 1, Méthode de franç	cais, Annie Berthe	t, Catherin	e Hugo, Véron	ique M.
	Kiziria	n, Béatrix Sampsonis, Moni	ique Waendendrie	s, Hachett	e livre 2006.	•
Mod	le of Ev	aluation: CAT / Assignmen	nt / Quiz / Seminar	:/ FAT		
Reco	ommen	ded by Board of Studies	26.02.2016			
App	roved b	y Academic Council	No.41	Date	17-06-2016	

SET 50 Pre-req		SCIENCE, EN									С
Pre-req			GINEERING AN	•	)	0	0		2		
Pre-req			PROJECT-2	[							1
	quisite					Sylla	ıbı	ıs V	Vei	rsio	n
Anti-re	equisite									]	1.10
Course	Objectives										
■ <sup>′</sup>	To inculcate	opportunity to involv research culture the rational and inno			ce / enginee	ring					
-	ed Course Completion of the	<b>Dutcome:</b> is course, the studen	t should be able to	:							
2.	Exhibit inde	plems that have releve pendent thinking and the application of re	l analysis skills								
Modali	ties / Requi	rements									
2. 2 3. 4.	Involve in lit Use Science, Adopt releva	r group projects can terature survey in the /Engineering princip ant and well-defined of scientific report in	e chosen field les to solve identif / innovative metho	dologies t		-	ïe	d ol	bje	ctiv	ve
Studen	t Assassman	t : Periodical review	ve oral/poster pras	ntation							
		Board of Studies	17-08-2017	mation							
		mic Council	No. 47	Date	05-10-201	7					

Course code		Course Title	e			L	Τ	P	Course code     L     T     P     J					
SET 5002	SCIENCE, EN	GINEERING AI PROJECT-		INOLOGY		0	0	0	0	2				
Pre-requisite					Syl	labı	us V	Ve	sic	m				
Anti-requisite									1	1.10				
<b>Course Objectives</b>	:													
1. To prov	ide opportunity to in	volve in research 1	related to s	science / eng	ineer	ing								
2. To incul	cate research culture	e												
3. To enha	nce the rational and	innovative thinkin	g capabili	ties										
<b>Expected Course</b>	Outcome:													
On completion of the	nis course, the studer	nt should be able to	o:											
1 Identify pr	oblems that have rele	evance to societal	/ industria	lneeds										
• •	lependent thinking a		maasuna	i needs										
	te the application of	•	engineerir	o principles										
Modalities / Requi	**	Tele valit selence /	engineerii	ig principies										
	al or group projects	can be taken up												
	in literature survey i													
	ence/Engineering pri		entified is	sues										
	elevant and well-d	-			fulfi	11 f	he	sn	eci	fied				
objectiv			ve memo		Tunn	11 U.		ЪЪ	001	neu				
0	sion of scientific repo	ort in a specified for	ormat (afte	er nlagiarism	chec	rk)								
	<b>nt</b> : Periodical review			r prugiurioni		·								
Recommended by I		17-08-2017												
Approved by Acade		No. 47	Date											

	le	Course title	L T P J C
STS 5001		Essentials of Business Etiquette and problem solving	3 0 0 0 1
Pre-requisi	ite	None	Syllabus version
Course Ob	inativas	•	
		the students' logical thinking skills	
		e strategies of solving quantitative ability problems	
		he verbal ability of the students	
		critical thinking and innovative skills	
E	1		
Expected C			a thomas lyses
	-	udents to use relevant aptitude and appropriate language to express nicate the message to the target audience clearly	ss themselves
		s will be able to be proficient in solving quantitative aptitude and	verbal ability
		f various examinations effortlessly	verbar ability
ques			
Module:1	Busin	ess Etiquette: Social and Cultural Etiquette and Writing	9 hours
-		any Blogs and Internal Communications and Planning and	
		ng press release and meeting notes	
plan, Progre	0	audience, Identifying, Gathering Information, Analysis, Determir	0
	your su	k, Types of planning, Write a short, catchy headline, Get to the P bject in the first paragraph., Body – Make it relevant to your audi	
Module:2			
Module:2	Study	bject in the first paragraph., Body – Make it relevant to your audi skills – Time management skills rastination, Scheduling, Multitasking, Monitoring, working unde	ence, <b>3 hours</b>
Module:2 Prioritizatio adhering to	Study n, Proc deadlin	bject in the first paragraph., Body – Make it relevant to your audi <b>skills – Time management skills</b> rastination, Scheduling, Multitasking, Monitoring, working unde es	ence, <b>3 hours</b> or pressure and
Module:2 Prioritizatio adhering to	Study on, Proc deadlin Prese	bject in the first paragraph., Body – Make it relevant to your audi <b>skills – Time management skills</b> rastination, Scheduling, Multitasking, Monitoring, working unde es <b>ntation skills – Preparing presentation and Organizing</b>	ence, 3 hours
Module:2 Prioritizatio adhering to	Study on, Proc deadlin Presen mater	bject in the first paragraph., Body – Make it relevant to your audi <b>skills – Time management skills</b> rastination, Scheduling, Multitasking, Monitoring, working unde es	ence, <b>3 hours</b> or pressure and
Module:2 Prioritizatio adhering to Module:3 10 Tips to p sky thinkin presentation posters, Set	Study on, Proc deadlin Prese mater with c orepare ng, Intr n, Impor tting ou	bject in the first paragraph., Body – Make it relevant to your audi skills – Time management skills rastination, Scheduling, Multitasking, Monitoring, working unde es ntation skills – Preparing presentation and Organizing rials and Maintaining and preparing visual aids and Dealing	ence, <b>3 hours</b> er pressure and <b>7 hours</b> ator Test, Blue plor, Strategic ence, Design of
Module:2 Prioritizatio adhering to Module:3 10 Tips to p sky thinkin presentation posters, Set questions, H	Study on, Proc deadlin Prese mater with o prepare ng, Intro tring ou Handling	bject in the first paragraph., Body – Make it relevant to your audi skills – Time management skills rastination, Scheduling, Multitasking, Monitoring, working unde es ntation skills – Preparing presentation and Organizing rials and Maintaining and preparing visual aids and Dealing questions PowerPoint presentation, Outlining the content, Passing the Eleva roduction , body and conclusion, Use of Font, Use of Co rtance and types of visual aids, Animation to captivate your audie ut the ground rules, Dealing with interruptions, Staying in or g difficult questions	ence, <b>3 hours</b> er pressure and <b>7 hours</b> ator Test, Blue plor, Strategic ence, Design of control of the
Module:2 Prioritizatio adhering to Module:3 10 Tips to p sky thinkin presentation posters, Set	Study on, Proc deadlin Prese mater with c orepare of ag, Intro- ng, Intro- tting of landling Quan	bject in the first paragraph., Body – Make it relevant to your audi <b>skills – Time management skills</b> rastination, Scheduling, Multitasking, Monitoring, working under es <b>ntation skills – Preparing presentation and Organizing</b> <b>rials and Maintaining and preparing visual aids and Dealing</b> <b>questions</b> PowerPoint presentation, Outlining the content, Passing the Elever roduction , body and conclusion, Use of Font, Use of Con- rtance and types of visual aids, Animation to captivate your audie ut the ground rules, Dealing with interruptions, Staying in o	ence, <b>3 hours</b> er pressure and <b>7 hours</b> ator Test, Blue plor, Strategic ence, Design of
Module:2 Prioritizatio adhering to Module:3 10 Tips to p sky thinkin presentation posters, Set questions, H Module:4	Study on, Proc deadlin Prese mater with o orepare n, Intro tring ou landling Quan Progr	bject in the first paragraph., Body – Make it relevant to your audi skills – Time management skills rastination, Scheduling, Multitasking, Monitoring, working under es ntation skills – Preparing presentation and Organizing rials and Maintaining and preparing visual aids and Dealing questions PowerPoint presentation, Outlining the content, Passing the Elever roduction , body and conclusion, Use of Font, Use of Con- rtance and types of visual aids, Animation to captivate your audie ut the ground rules, Dealing with interruptions, Staying in or g difficult questions titative Ability -L1 – Number properties and Averages and ressions and Percentages and Ratios	ence, 3 hours er pressure and 7 hours ator Test, Blue plor, Strategic ence, Design of control of the 11 hours
Module:2 Prioritizatio adhering to Module:3 10 Tips to p sky thinkin presentation posters, Set questions, F Module:4 Number of	Study on, Proc deadlin Presen mater with o orepare in n, Impor thing out Handling Quan Progr factors	bject in the first paragraph., Body – Make it relevant to your audi skills – Time management skills rastination, Scheduling, Multitasking, Monitoring, working unde es ntation skills – Preparing presentation and Organizing rials and Maintaining and preparing visual aids and Dealing questions PowerPoint presentation, Outlining the content, Passing the Elever roduction , body and conclusion, Use of Font, Use of Con- rtance and types of visual aids, Animation to captivate your audie aut the ground rules, Dealing with interruptions, Staying in or g difficult questions titative Ability -L1 – Number properties and Averages and ressions and Percentages and Ratios s, Factorials, Remainder Theorem, Unit digit position, Tens	ence, 3 hours er pressure and 7 hours ator Test, Blue olor, Strategio ence, Design of control of the 11 hours digit position
Module:2 Prioritizatio adhering to Module:3 10 Tips to p sky thinkin presentation posters, Set questions, F Module:4 Number of Averages,	Study on, Proc deadlin Presen mater with c orepare ng, Intro- ng, Intro- tring ou landling Quan Progr factors Weight	bject in the first paragraph., Body – Make it relevant to your audi skills – Time management skills rastination, Scheduling, Multitasking, Monitoring, working under es ntation skills – Preparing presentation and Organizing rials and Maintaining and preparing visual aids and Dealing questions PowerPoint presentation, Outlining the content, Passing the Elever roduction , body and conclusion, Use of Font, Use of Con- rtance and types of visual aids, Animation to captivate your audie ut the ground rules, Dealing with interruptions, Staying in or g difficult questions titative Ability -L1 – Number properties and Averages and ressions and Percentages and Ratios	ence, 3 hours er pressure and 7 hours ator Test, Blue blor, Strategie ence, Design o control of the 11 hours digit position on, Harmonic

Mo	dule:5	Reasoning Ability-L1 – Analytical Reasoning	8 hours
		gement (Linear and circular & Cross Variable Relationship), Blood Relationship, Blood Relationship/grouping, Puzzle test, Selection Decision table	ons,
Mo	dule:6	Verbal Ability-L1 – Vocabulary Building	7 hours
•	-	& Antonyms, One-word substitutes, Word Pairs, Spellings, Idioms, Sente , Analogies	nce
		Total Lecture hours:	45 hours
Ref	erence l	Books	
1.	Tools f	Patterson, Joseph Grenny, Ron McMillan, Al Switzler (2001) Crucial Conv For Talking When Stakes are High. Bangalore. McGraw-Hill Contemporary	/
2.	Dale C Books	Carnegie, (1936) How to Win Friends and Influence People. New York	k. Gallery
3.	Scott P	eck. M (1978) Road Less Travelled. New York City. M. Scott Peck.	
4.	FACE	(2016) Aptipedia Aptitude Encyclopedia. Delhi. Wiley publications	
5.	ETHN	US (2013) Aptimithra. Bangalore. McGraw-Hill Education Pvt. Ltd.	
We	bsites:		
1.	www.c	halkstreet.com	
2.	www.s	killsyouneed.com	
3.	www.n	nindtools.com	
4.	www.tl	hebalance.com	
5.	www.e	guru.000	
		valuation: FAT, Assignments, Projects, Case studies, Role plays, nts with Term End FAT (Computer Based Test)	

Course code	Course title	L T P J C
STS 5002	Preparing for Industry	3 0 0 0 1
Pre-requisite	None	Syllabus
		version
<u>a</u>		1
Course	1. To challenge students to explore their problem-solving	
<b>Objectives:</b>	2. To develop essential skills to tackle advance quantitativ	e and verbal
	ability questions 3. To have working knowledge of communicating in Engl	ich
	5. To have working knowledge of communicating in Engl	.1511
Expected Course	1. Enabling students to simplify, evaluate, analyze and use	e functions and
Outcome:	expressions to simulate real situations to be industry real	
	2. The students will be able to interact confidently and use de	
	models effectively	
	3. The students will be able to be proficient in solving qua	
	aptitude and verbal ability questions of various examination	ations
	effortlessly	
Module:1	Interview skills – Types of interview and Techniques to	3 hours
mouule.1	face remote interviews and Mock Interview	5 nours
	face remote miler views and work miler view	
Structured and unst	ructured interview orientation, Closed questions and hypothetica	al questions,
	ective, Questions to ask/not ask during an interview, Video inter	
	, Phone interview preparation, Tips to customize preparation for	personal
interview, Practice	rounds	
Module:2	Degume skills Degume Templete and Use of newer	2 hours
Module:2	<b>Resume skills – Resume Template and Use of power</b> verbs and Types of resume and Customizing resume	2 nours
	verbs and Types of resume and Customizing resume	
	dard resume, Content, color, font, Introduction to Power verbs	
	resume, Frequent mistakes in customizing resume, Layout -	Understanding
different company's	s requirement, Digitizing career portfolio	
Module:3	Emotional Intelligence - L1 – Transactional Analysis and	12 hours
Wibuule.5	Brain storming and Psychometric Analysis and Rebus	12 11001 5
	Puzzles/Problem Solving	
Introduction, Con	tracting, ego states, Life positions, Individual Brainsto	rming, Group
	pladder Technique, Brain writing, Crawford's Slip writing app	
	r bursting, Charlette procedure, Round robin brainstormir	
Personality Test, M	ore than one answer, Unique ways	
Module:4	Quantitative Ability-L3 – Permutation-Combinations	14 hours
	and Probability and Geometry and mensuration and	
	Trigonometry and Logarithms and Functions and	
	Quadratic Equations and Set Theory	
Counting C :	Lincon Amongoment Circular As	al Dra-11-11'
Counting, Grouping	ng, Linear Arrangement, Circular Arrangements, Condition	al Probability
<b>U</b> 1	ependent Events, Properties of Polygon, 2D & 3D Figures, Ar	•

U U	ances, Simple trigonometric functions, Introduction to logarithms, oduction to functions, Basic rules of functions, Understand	
Equations, Rules	& probabilities of Quadratic Equations, Basic concepts of Venn D	iagram
Module:5	Reasoning ability-L3 – Logical reasoning and Data Analysis and Interpretation	7 hours
	ry logic, Sequential output tracing, Crypto arithmetic, Data Sufficienced, Interpretation tables, pie charts & bar chats	ency, Data
Module:6	Verbal Ability-L3 – Comprehension and Logic	7 hours
<b>U</b> 1	nension, Para Jumbles, Critical Reasoning (a) Premise and Conclus ference, (c) Strengthening & Weakening an Argument	45 hours
	Total Lecture hours:	45 nours
References	<ul> <li>Michael Farra and JIST Editors(2011) Quick Resume &amp; Book: Write and Use an Effective Resume in Just One Paul, Minnesota. Jist Works</li> <li>Daniel Flage Ph.D(2003) The Art of Questioning: An In Critical Thinking. London. Pearson</li> <li>FACE(2016) Aptipedia Aptitude Encyclopedia.Delhi. V publications</li> </ul>	Day. Saint
	tion: FAT, Assignments, Projects, Case studies, Role plays,	
3 Assessments w		

Course Code	Course Title	L	Т	Р	J	С
ECE6099	Masters Thesis		0	0	0	16
Pre-requisite	As per the academic regulations Syllabus		vers	sion		
		1.0				

### **Course Objectives:**

To provide sufficient hands-on learning experience related to the design, development and analysis of suitable product / process so as to enhance the technical skill sets in the chosen field.

### **Expected Course Outcome:**

At the end of the course the student will be able to

- 1. Formulate specific problem statements for ill-defined real life problems with reasonable assumptions and constraints.
- 2. Perform literature search and / or patent search in the area of interest.
- 3. Conduct experiments / Design and Analysis / solution iterations and document the results.
- 4. Perform error analysis / benchmarking / costing
- 5. Synthesise the results and arrive at scientific conclusions / products / solution
- 6. Document the results in the form of technical report / presentation

### Contents

Capstone Project may be a theoretical analysis, modeling & simulation, experimentation & analysis, prototype design, fabrication of new equipment, correlation and analysis of data, software development, applied research and any other related activities.

Project should be for two semesters based on the completion of required number of credits as per the academic regulations.

Should be individual project.

In case of group projects, the individual project report of each student should specify the individual's contribution to the group project.

Carried out inside or outside the university, in any relevant industry or research institution.

Publications in the peer reviewed journals / International Conferences will be an added advantage

Mode of Evaluation: Periodic reviews, Presentation, Final oral viva, Poster submission								
Recommended by Board of 10-06-2015								
Studies								
Approved by Academic Council	No. 37	Date	16-06-2015					

Course Code	Course Title	L	Т	Р	J	С
ECE5014	ASIC DESIGN	3	0	2	0	4
Pre-requisite	Nil					

### **Course Objective :**

The course is aimed to

- 1. explain the types of ASIC and typical ASIC design Flow.
- 2. give the students an understanding of HDL coding guidelines and synthesizable HDL constructs.
- 3. explain the RTL synthesis Flow with respect to different cost function.
- 4. teach the various timing parameter and how to perform Static Timing Analysis for ASIC chips.
- 5. discuss the various abstraction levels in physical design and guidelines at each abstraction level.
- provide detailed insight on importance of physical design verification 6.

### **Expected Course Outcome :**

At the end of the course the student will be able to

- 1. Understand different types of ASICs and design flows.
- 2. Design digital systems by adhering to synthesizable HDL constructs.
- 3. Synthesize the given design by considering various constraints and to optimize the same.
- 4. Understand various timing parameters and compute computation time for a given design using static timing analysis.
- 5. Perform physical design by adhering to guidelines.
- 6. Apprehend the importance of physical design verification.
- 7. Design ASIC based systems using industry standard tools.

#### ASIC Design Methodology & Design Flow Module:1

Implementation Strategies for Digital ICs: Custom IC Design- Cell-based Design Methodology -Array based implementation approaches - Traditional and Physical Compiler based ASIC Flow.

#### Module:2 Verilog HDL Coding Style for Synthesis

HDL Coding style - Guidelines and Recommendation - FSM Coding Guideline and Coding Style for Synthesis.

#### Module:3 **RTL Synthesis**

RTL synthesis Flow - Synthesis Design Environment & Constraints - Architecture of Logic Synthesizer - Technology Library Basics- Components of Technology Library -Synthesis Optimization- Technology independent and Technology dependent synthesis- Data path Synthesis – Low Power Synthesis - Timing driven synthesis- Formal Verification.

#### Module:4 **Timing Parameters**

Timing Parameter Definition – Setup Timing Check- Hold Timing Check- Multicycle Paths- False Paths - Clocking of Synchronous Circuits.

#### **Static Timing Analysis** Module:5

Timing Analysis - Clock skew optimization - Clock Tree Synthesis.

#### Module:6 **Physical Design**

Detailed step in Physical Design Flow- Guidelines for Floor plan, Placement and routing. Conducting layers and their characteristics - Cell-based back-end design -ECO - Packaging-Layout Issues-Preventing electrical overstress.

5 hours

7 hours

8 hours

8 hours

6 hours

Modul		Physical Design Verification		5 hours
Static v	verifica	tion techniques-Post-layout design verificatio	n.	
Modul	le:8	Contemporary issues:		2 hours
				451
		Total Lecture hours:		45 hours
Text B	eok(a)			
1.		nshuBhatnagar, Advanced ASIC Chip Synthe	sis Kluwer Academic Publishe	r Second
1.		on, 2012.	sis, Ruwer Academic Fublishe.	, second
Refere	ence Bo			
1.		Brunvand, Digital VLSI Chip Design with Ca	dence and Synopsys CAD Too	ls Addisor
1.		ey, First Edition, 2010.	achee and Synopsys Crib 100.	is, 7 <b>id</b> disoli
2.		asker and RakeshChadha, Static Timing Anal	vsis for Nanometer Designs, St	oringer US
		Edition, 2010.	,,	
Mode	of Eva	luation:Continuous Assessment Test -I (C.	AT-I), Continuous Assessmen	nt Test –I
		ninar / Challenging Assignments / Completion		
		ndustrial problems, Final Assessment Test (F.		C C
List of	Challe	enging Experiments (Indicative)		
1.	Phase	e- I Design of digital architecture		12 hours
		n Specification: Starting with the soda mach	ine dispenser design described	
	in lect	ture, create a block diagram and high-level sta	ate machine for a soda machine	
	disper	nser that has a choice of two soda types, and t	that also provides change to the	
		mer. A coin detector provides the circuit with	-	
		ne clock cycle when a coin is detected, and		
		s value in cents. Two 8-bit input s1 and s2 in		
		es. The user's soda selection is controlled b	•	
		pushed will output 1 for one clock cycle. I		
	Ŭ	e for their selection, the circuit should set eit	1	
		lock cycle, causing the selected soda to be		
		t should also set an output bit cr to 1 for		
	-	red, and should output the amount of chan t ca. Use the RTL design method to convert the	0 1 0	
	-	oller and a data path. Design the data path	0	
		oller to the point of an FSM only.	in to structure, but design the	
2.		e-II Logical Synthesis of digital architecture	P	6 hours
2.		y design and timing constraints :	~	0 110415
		ig constraints: set_clock ,set_clock_uncertaint	ty, set clock latency.	
		lock_transition, set_input_delay, set_output_d		
		ulticycle_path.	······································	
		constraints are: set_max_fanout, set_max_tra	nsition and	
		ax_capacitance.		
		nization constraints :set_max_area, set_min_a	rea,	
	-	ax_leakegeandset_max_dynamic.		
3.		e-III Netlist Optimization and Formal Veri	ification	4 hours
		y power optimization constraints, Gate Level S		
		cation of digital architecture.		
4.	Phase	e-IV Physical Synthesis of digital architectu	ire	4 hours
	1 .	e_floorplan, set_propgated_clock,preroute_sta	ndard calls sat route art	1

5. Phase - VPhysical Verification of digital architecture						
set_fix_multiple_port_nets, write_physical_constraints and write_parasitics						
	Total Laboratory hours: 30 hours					
Mode	Mode of Evaluation: Continuous assessment of challenging experiments /Final Assessment Test					
(FAT).						
Recom	Recommended by Board of Studies 13-12-2015					
Approv	Approved by Academic CouncilNo. 4018-03-2016					

Course Code	Course Title	L T P J C
ECE5015	DIGITAL IC DESIGN	3 0 0 4 4
Pre-requisite	Nil	

### **Course Objective :**

The course is aimed to

- 1. apply the models for state-of-the-art VLSI components, fabrication steps, hierarchical design flow and semiconductor business economics to judge the manufacturability of a design and assess its manufacturing costs.
- 2. focus on the systematic analysis and design of basic digital integrated circuits in CMOS technology.
- 3. enhance problem solving and creative circuit design techniques.
- 4. emphasize on the layout design of various digital integrated circuits.
- 5. focus on the methodologies and design techniques related to digital integrated circuits.

### **Expected Course Outcome :**

At the end of the course the student will be able to

- 1. Understand design metric and MOS physics
- 2. Design layout for various digital integrated circuits.
- 3. Design the CMOS inverter with optimized power, area and timing.
- 4. Design static and dynamic digital CMOS circuits.
- 5. Understand the timing concepts in latch and flip-flops.
- 6. Design CMOS memory arrays.
- Understand interconnect and clocking issues. 7.

### Module:1 Introduction:

Issues in Digital IC Design- Quality Metrics of a Digital Design - MOS Transistor Theory.

Module:2 | Fabrication Technologies:

VLSI Manufacturing Process Steps - Crystal Growth - Wafer cleaning - Oxidation - Thermal Diffusion - Ion Implantation - Lithography -Epitaxy - Metallization -Dry and Wet etching and Packaging.

Fabrication of MOSFET with Metal Gate and Self-aligned Poly-Gate Processes with details on CMOS Design Rules and Layouts, Fabrication of CMOS inverter with details on Design Rules and Layouts.

### Module:3 | The CMOS Inverter:

5 hours

8 hours

Static CMOS Inverter- Static and Dynamic Behavioural Practices of CMOS Inverter - Noise Margin.

Components of Energy and Power - Switching -Short-Circuit and Leakage Components. Technology scaling and its impact on the inverter metrics - Passive and Active Devices.

## Module:4 | Static & Dynamic CMOS Design:

Complementary CMOS -Ratioed Logic (Pseudo NMOS, DCVSL) - Pass Transistor Logic -Transmission gate logic - Dynamic Logic Design Considerations - Speed and Power Dissipation of Dynamic logic -Signal integrity issues -Domino Logic.

Module:5 | CMOS Sequential Logic Circuit Design: 5 hours Introduction - Static Latches and Registers - Dynamic Latches and Registers - Pulse Based

3 hours

Registers - Sense Amplifier based registers -Latch vs. Register based pipeline structures.

Module:6 Designing Memory & Array structures: SRAM and DRAM Memory Core - memory peripheral circuitry - Memory reliability and yield -Power dissipation in memories.

### Module:7 Interconnects and Timing Issues:

8 hours Resistive, Capacitive and Inductive Parasitics - Computation of R, L and C for given interconnects - Buffer Chains - Timing classification of digital systems - Synchronous Design - Origins of Clock Skew/Jitter and impact on Performance - Clock Distribution Techniques - Latch based clocking - Synchronizers and Arbiters -Clock Synthesis and Synchronization using a Phase-Locked Loop.

#### **Contemporary issues:** Module:8

2 hours

	Total Lecture hours:	45 hours
Text	Book(s)	
1. J	Jan M. Rabaey, AnanthaChadrakasan, BorivojeNikolic, Digital Integrated C	Circuits: A
]	Design Perspective, PHI, Second Edition, 2016.	
	Neil.H, E.Weste, David Harris, Ayan Banerjee, CMOS VLSI Design: A C	Circuit and
	Systems Perspective, Pearson Education, Fourth Edition, 2011.	
	rence Books	
	Sung-Mo Kang, Yusuf Leblebici, CMOS Digital Integrated Circuits - An	alysis and
	Design, McGraw-Hill, Fourth Edition, 2014.	
	Sorab K Gandhi, VLSI Fabrication Principles: Si and GaAs, John Wiley and So	ns, Second
	Edition, 2010.	
	e of Evaluation:Continuous Assessment Test -I (CAT-I), Continuous Assessment	
	T-II), Seminar / Challenging Assignments / Completion of MOOC / Innovative	ideas leading
	utions for industrial problems, Final Assessment Test (FAT).	
	of Projects (Indicative)	
	. Design and simulate a 16-bit comparator by using 8T full adders	
	. Pass transistor logic based ALU design using low power full adder design	
	. Design of high performance power efficient flip-flop using transmission gates	
	. Design of high performance 5:32 decoder using 2:4,3:8 mixed logic line deco	ders.
	. Design of current comparator using FINFET	
6	. Analysis of leakage current and leakage power reduction during reduction	on in CMOS
	SRAM cell	
	. Design of encoder for a 5GS/S 5 bit flash ADC	
8	. Design a 65 nm reliable 6T CMOS SRAM cell with minimum size transistors	8
Mode	e of Evaluation:Review I, II and III	
<b>D</b>	12 12 2015	

Recommended by Board of Studies	13-12-2015			
Approved by Academic Council	No. 40	18-03-2016		

Course Code	Course Title	L T P J C
ECE5016	ANALOG IC DESIGN	3 0 2 0 4
Pre-requisite	Nil	

### **Course Objectives :**

The course is aimed to

- 1. analyze and design single-ended and differential IC amplifiers.
- 2. understand the relationships between devices, circuits and systems.
- 3. emphasize the design of practical amplifiers, small systems and their design parameter trade-offs.

### **Expected Course Outcome :**

At the end of the course the student will be able to

- 1. Analyse low-frequency characteristics of single-stage amplifiers and differential amplifiers.
- 2. Analyse high-frequency response and noise of amplifiers.
- 3. Understand the feedback concepts.
- 4. Analyse and Design of High Gain Amplifiers.
- 5. Understand stability analysis and frequency compensation techniques of amplifiers.
- 6. Understand the basic concepts, non-idealities and applications of PLLs.
- 7. Design and characterize amplifiers according to design specifications in Cadence CAD software.

### Module:1 | Current source and Amplifier design:

MOS Device models, MOS Current Sources and Sinks, Current Mirror: Basic Current Mirrors, Cascode current Mirrors. Bandgap references. Single stage Amplifies: Basic concepts, Common Source stage, Common Gate stage, Cascode stage. Differential stage: Single ended and Differential operation. Basic Differential Pair.

Module:2	Frequency response and Noise analysis of Amplifiers:	8 hours
Millen offer	t Engrand and an of Common Source store. Common Cote store	Casaada stasa

Miller effect, Frequency response of Common Source stage, Common Gate stage, Cascode stage and Differential pair. Noise in Amplifiers: Common Source stage, Common Gate stage, Cascode stage, Differential pair. Noise Bandwidth.

### Module:3 | Feedback Amplifiers:

Ideal feedback equation, Gain sensitivity, Effect of Negative Feedback on Distortion, Types of Feedback Amplifiers. Feedback configurations: voltage-voltage, current-voltage, current-current, voltage-current feedback. Practical configurations and Effect of loading.

### Module:4 **Operational Amplifier**

Common mode Feedback circuits, Op Amp CMRR requirements, Need for Single and Multistage amplifiers, Effect of loading in Differential stage. Performance Analysis: DC gain, Frequency response, Noise, Mismatch, Slew rate of cascode and two stage Op Amps, Fully Differential Op Amps, Common-Mode feedback loop stability.

### Module:5 | Stability analysis

Basic Concepts, Instability and the Nyquist Criterion, Stability Study for a Frequency-Selective Feedback Network, Effect of Pole Locations on Stability

4 hours

8 hours

8 hours

Mo	dule:6	Frequency compensation			4 hours
		Compensation: Concepts and Techn			
pol	e, Miller	Compensation, Compensation of I	Miller RHP Zero, Nested M	Ailler, Comp	ensation of
two	stage O	P Amps.			
	dule:7	Phase Locked Loops			4 hours
		Lock acquisition, Phase Detector,			
No	n-ideal e	ffects in PLL: PFD/CL non idealiti	ies, Jitter, Delay Locked Lo	oop, Applica	tions.
Mo	dule:8	Contemporary issues:			2 hours
IVIU	uuit.o	Contemporary issues.			2 11001 5
			Total Lectu	ure hours:	45 hours
То	kt Book(		Totul Leen		
1.		s) IRazavi, Design of Analog CMOS	Integrated Circuits McG	row Hill So	cond Edition
1.	2017.	ikazavi, Desigli of Allalog Civios	integrated circuits, MeO	law-1111, 50	cond Edition,
2.		Johns and Ken Martin, Analog In	ntegrated Circuit Design, J	ohn Wiley	& Sons. Inc
		Edition, 2012.		j	,,
Ref	ference				
1.	Phillip	E. Allen and Douglas R. Holberg	, CMOS Analog Circuit D	esign, Oxfo	rd University
	-	UK, Second Edition, 2010.	, 8	8	5
2.	R. Jac	ob Baker, CMOS Circuit Design	n, Layout and Simulation	n, IEEE Pre	ss Series on
		lectronic Systems, Wiley Publicati			
Mo	de of E	valuation:Continuous Assessment	Test -I (CAT-I), Continu	ious Assessr	nent Test –II
(CA	AT-II), S	eminar / Challenging Assignments	s / Completion of MOOC /	/ Innovative	ideas leading
to s	olutions	for industrial problems, Final Asse	essment Test (FAT).		
		llenging Experiments (Indicative			
1	-	is and Design of Common Source	-	nnected	4 hours
		nd Suggest a Circuit to achieve hig			
2		is and Design of Common Gate A	1		4 hours
		t Source load. Justify the results in	n terms of input impedance	e of the	
	circuit.				
3	-	is and Design of Simple Current	Mirror and Suggest a cir	cuit to	4 hours
4		ze the error in the output current.	1.01 A 1	1 1	<u> </u>
4		is and Design of Differential A	Amplifier with Active loa	ad and	6 hours
~		t Source Load.	1'6' 1.0 ( 0'	• •	4.1
5	-	is and Design of Cascode Amp		cuit to	4 hours
6		me Voltage Headroom Limitation. is and Design of Two-Stage Opam		ention	8 hours
U	Anarys	is and Design of Two-Stage Opani	Total Laboratory		30 hours
Mo	de of Ev	aluation:Continuous assessment of			
	at of Ev	aruation. Continuous assessment of	chanenging experiments /	r mai Assess	ment rest
	,	ded by Board of Studies	13-12-2015		
		y Academic Council	No. 40	18-03-2016	<u>.</u>
Δp			110. TU	10 05-2010	,

<b>Course Code</b>	Course Title	<b>ר</b>	ſ	P	J	С
ECE5017	DIGITAL DESIGN WITH FPGA 2	0	,	2	4	4
Pre-requisite	Nil	1	_			
<b>Course Objectives :</b>						
The course is aimed	1 to					
1. understand the behavioral level	various abstraction levels in Verilog HDL and thus model tasks & l.	fu	no	ctic	ons	at
and sequential l	e machines using D and JK Flip Flops and design the complex cologic circuits using various constructs in Verilog.					
	types programmable logic devices and building blocks of FPG design using Xilinx and ALTERA FPGAs.	ίA	a	nd	tł	nus
Expected Course Out	come :					
At the end of the course	e the student will be able to					
	ious abstraction levels in Verilog HDL.					
-	te machine using D and JK Flip Flop.					
1	al circuit using behavioural modelling.					
-	plex combinational and sequential logic circuits using various const	tru	ct	S 11	1	
Verilog.	aromushla lagia daviana and various blasks avist in EDCA					
-	grammable logic devices and various blocks exist in FPGA. architectural and resource difference between ALTERA and Xilinx.					
6	b) design complex combinational and sequential circuits.					
	bototype digital systems design using FPGA.					
o. develop and pre						
Module:1 Veril	og HDL – Data Flow & Structural Modeling			6 h	101	irs
	Ports and Modules – Operators - Gate Level Modeling - Data Flow	M				
	iler Directives - Test Bench.					, 
Module:2 State	Machine Design			4 h	101	irs
	ichines -State machine as a sequential controller- Analysis of sta	te				
	p-flops - Design of state machines- State table and State as					
	able - excitation maps and equations - logic realization- Desig		-			
	ial adder, Vending machine.				-	
Module:3 Veril	og HDL – Behavioral Modeling			5 h	οι	ırs
viluation vill			_	1	·ki	ing
Behavioral level Mo	deling- Procedural Assignment Statements- Blocking and Ne	on	-E	510		
Behavioral level Mo	Functions - Useful Modeling Techniques.	on	-E	510		
Behavioral level Mo Assignments -Tasks & Module:4 Veril	Functions - Useful Modeling Techniques.         log Modeling of Combinational Circuits	on		4 h		irs
Behavioral level Mo Assignments -Tasks & Module:4 Veril	Functions - Useful Modeling Techniques.	on				irs
Behavioral level MoAssignments -Tasks &Module:4VerilBehavioral, Data FlowModule:5Veril	Functions - Useful Modeling Techniques.         log Modeling of Combinational Circuits         and Structural Realization of Adders and Multipliers         log Modeling of Sequential Circuits			4 h 4 h	101	irs irs
BehaviorallevelMoAssignments-Tasks &Module:4VerilBehavioral, DataFlowModule:5VerilSynchronous and Asy	Functions - Useful Modeling Techniques.         log Modeling of Combinational Circuits         and Structural Realization of Adders and Multipliers			4 h 4 h	101	
BehaviorallevelMoAssignments-Tasks &Module:4VerilBehavioral, DataFlowModule:5VerilSynchronous and Asymodeling of Sequence	Functions - Useful Modeling Techniques.         Iog Modeling of Combinational Circuits         and Structural Realization of Adders and Multipliers         Iog Modeling of Sequential Circuits         nchronous FIFO – Single port and Dual port ROM and RAM - FSM         e detector - Serial adder - Vending machine.		/e	4 h 4 h erilo	101 101 0g	ırs
BehaviorallevelMoAssignments-Tasks &Module:4VerilBehavioral, DataFlowModule:5VerilSynchronous and Asymodeling of SequenceModule:6FPG.	Functions - Useful Modeling Techniques.         log Modeling of Combinational Circuits         and Structural Realization of Adders and Multipliers         log Modeling of Sequential Circuits         nchronous FIFO – Single port and Dual port ROM and RAM - FSM	1 V	/e	4 h 4 h erilo 3 h		irs

Module:	7 Xilinx and ALTERA FPGAs	2 hours
Xilinx V	irtex 5.0 Architecture - Xilinx Virtex VI Architecture - ALTERA Cyclone II	Architecture -
ALTERA	A Stratix IV Architecture.	
Module:	8 Contemporary issues:	2 hours
	Total Lecture hours:	30 hours
Text Bo	bk(s)	
1.	Ming-Bo Lin, Digital Systems Design and Practice: Using Verilog HDL and	FPGAs, Create
	Space Independent Publishing Platform, Second Edition, 2015.	
2.	Michael D Ciletti, Advanced Digital Design with the Verilog HDL, Prentic	e Hall, Second
	Edition, 2011.	
Referen		
1.	Wayne Wolf, FPGA Based System Design, Prentices Hall Modern Semico	nductor Desigr
-	Series, 2011.	
2.	Charles H Roth Jr, Lizy Kurian John and Byeong Kil Lee Digital System	s Design using
	Verilog, Cengage Learning, First Edition, 2016.	T I CAT
	Evaluation: Continuous Assessment Test –I (CAT-I), Continuous Assessment	
	nar / Challenging Assignments / Completion of MOOC / Innovative ideas lead	ing to solution
	trial problems, Final Assessment Test (FAT).	
	hallenging Experiments (Indicative)	4 1
1.	Many ink-jet printers have six cartridges for different colored ink: black,	4 hours
	cyan, magenta, yellow, light cyan and light magenta. A multibit signal in	
	such a printer indicates selection of one of the colors. Write a data flow	
	Verilog model for a decoder for use in the inkjet printer described above.	
	The decoder has three input bits representing the choice of color cartridge and six output bits, one to select each cartridge. Verify the output of the	
	design using test bench by simulating in Modelsim Simulator. Implement	
2.	the design in ALTERA DE2-115 Board and verify it's functionality.	4 hours
Ζ.	Write a behavioral Verilog code to divide the ALTERA DE2-115 Board	4 110015
	clock frequency 50MHz by 40MHZ, 30MHz, 20 MHz, 10MHz. Display each of the output using LEDs available in the board.	
3.	Design and implement a circuit on the DE2-115 board that acts as a time-of-	4 hours
5.	day clock. It should display the hour (from 0 to 23) on the 7-segment	4 110015
	displays HEX7–6, the minute (from 0 to 60) on HEX5–4 and the second	
	(from 0 to 60) on HEX3–2. Use the switches $SW15-0$ to preset the hour and	
	minute parts of the time displayed by the clock.	
4.	We wish to implement a finite state machine (FSM) that recognizes two	8 hours
1.	specific sequences of applied input symbols, namely four consecutive 1s or	onours
	four consecutive 0s. There is an input w and an output z. Whenever $w = 1$ or	
	w = 0 for four consecutive clock pulses the value of z has to be 1; otherwise,	
	z = 0. Overlapping sequences are allowed, so that if $w = 1$ for five	
	consecutive clock pulses the output z will be equal to 1 after the fourth and	
	fifth pulses. Design and Implement the design using DE2-115 Board.	
	The pulses. Design and implement the design using DLL 115 Dould.	
5.	Write a behavioral Verilog code to design FIFO with the following	10 hours
- •	specification	

				n	
	d_in: input data; 8 bit width is cons				
	d_out: output data; 8 bit width is c				
	w_en: write enable signal				
	r_en: read enable signal				
	r_next_en: read next enable				
	w_next_en: write next enable				
	w_clk: write clock; 10 MHz for the	is design			
	r_clk: read clock; 50 MHz for this	design			
	w_ptr: write address pointer; 4 bit	to address depth of 16 $\cdot$			
	r_ptr: read address pointer; 4 bit to	address depth of $16 \cdot$			
	ptr_diff: address pointer difference	e; 4 bit width			
	f_full_flag: FIFO full flag; asserted	d when FIFO is full $\cdot$			
	f_empty_flag: FIFO empty flag; as	sserted when FIFO is empty			
	Use Dual Port RAM available in	ALTERA IP library to realiz	e the FIFO.		
	Implement the design using ALTE	RA DE2-115 board.			
		Total Labora	tory hours:	30 hours	
Mode o	f Evaluation: Continuous assessm	ent of challenging experiment	nts / Final A	ssessment Test	
(FAT).					
List of I	Projects (Indicative)				
1. I	Design MIPS 32-Bit RISC Processor	r and implement it using ALTE	ERA Cyclone	IV FPGA and	
s	tudy about it's performance.		-		
2. I	Design a Reconfigurable FIR Filter a	and verify it's functionality thr	ough test ben	ch. Implement	
	he design using ALTERA Cyclone		-	-	
3. Design and Implementation of Smart Traffic Light System for congested four way road					
	ALTERA Cyclone IV FPGA.				
4. Design and Implementation of CORDIC Algorithm using ALTERA Cyclone IV FPGA.					
	Evaluation: Review I, II & III		-		
-	nended by Board of Studies	13-12-2015			
Approve	ed by Academic Council	No. 40	18-03-2016		
Appion					

Course code     Course Title     L     T     P     J					
ECE 5018	Physics of VLSI Devices	3 0 0 3			
Pre-requisite	None	Syllabus version			
		v.1.1			
<b>Course Objectives</b>					
The course is aime					
1	ndamentals of intrinsic, extrinsic semiconductors with carrier c	oncentration,			
0 1	hysics of various carrier current transport mechanisms	MOGFET			
	ed physics and modeling of PN Junction, MOS capacitors, and uss in detail the short channel effects and the issues of UDSM				
5. Review and disc	uss in detail the short channel effects and the issues of ODSM				
Expected Course	Autcome :				
	ourse the student will be able to				
	sic semiconductors with specific carrier concentrations and, un	derstand the band			
-	liagrams of semiconductors.				
	model the carrier transport mechanism in semiconductors.				
	nctions of given specifications				
4. Model MOS	• •				
	FETs and model the MOSFETs				
6. Mitigate the s	hort channel effects and design UDSM transistors				
Module:1 Semic	conductor Physics	5 hours			
	olids - Intrinsic and Extrinsic semiconductors - Direct and Ir				
-	- Fermi distribution -Free carrier densities - Boltzmann sta	tistics - Thermal			
equilibrium.					
Madala 2 Carri	en Tresser en die Genericans de de m	4 1			
	er Transport in Semiconductors anisms: Drift current, Diffusion current - Mobility of carriers	4 hours			
equations - Continu		- Current density			
equations contine					
Module:3 P-N J	unctions	5 hours			
	m physics - Energy band diagrams - Space charge layers - P				
-	d Potentials - p-n junction under applied bias - Statio	-			
	-n junctions - Breakdown mechanisms.	C			
Module:4 MOS	Capacitor	8 hours			
	epletion - Strong inversion - Threshold voltage - Contact pote				
function - Oxide ar	nd Interface charges - Body effect - C-V characteristics of MOS	5			
		01			
	FETs and Compact Models	8 hours			
	uration voltage - Sub-threshold conduction - Effect of gate and	-			
•	Compact models for MOSFET and their implementation in S l parameters in SPICE.	FICE. Level 1, 2			
Module:6 Scalir	ng and Short Channel Effects	6 hours			
	- Channel length modulation - Punch-through - Hot carri				

Effect of scaling - Channel length modulation - Punch-through - Hot carrier degradation - MOSFET breakdown - Drain-induced barrier lowering.

	JDSM.	Sate structures in		puer una renaemity ena	nenges	
Mo	dule:8 Contemporary issues:			2 ho	ours	
Tot	al Lecture hours:			45 h	ours	
Tey	at Book(s)					
1.	Ben G. Streetman and S. Banerje	e, Solid State Ele	ctronic Dev	ces, Pearson Education	n, U.S,	
	Seventh Edition, 2014.					
2.	J.P. Colinge and C. A. Colinge	e, Physics of Sen	niconductor	Devices, Kluwer Aca	ademic	
	Publishers, US, 2017.					
Ref	erence Books					
1.	Y.P. Tsividis and Colin McAndre	w, Operation and I	Modelling o	f the MOS Transistor,	Oxford	
	University Press, US, Third Editio	on, 2011.				
2.	M K Achutan and K N Bhatt, Fundamental of Semiconductor Devices, McGraw Hill					
	Education, US, 2017.					
Mo	de of Evaluation: CAT / Assignmer	nt / Quiz / FAT				
Dec	commended by Board of Studies	05-10-2017				
	proved by Academic Council	No. 47		05-10-2017		
лμ	Noved by Academic Council	110.47		55-10-2017		

## Module:7 UDSM Transistor Design Issues

7 hours Effect of tox - Effect of high-k and low-k dielectrics on the gate leakage and Source and drain leakage - tunneling effects - Different gate structures in UDSM - Impact and reliability challenges iı

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Course Code	Course Title	L T P J C
ECE5019	COMPUTER AIDED DESIGN FOR VLSI	3 0 0 0 3
Pre-requisite	Nil	

**Course Objective :** 

The course is aimed to

- 1. imbibe the students with the fundamentals of graphs, the relevance and, their applications to VLSI design automation.
- 2. introduce the students with relevant examples the estimation of computational complexity and the general classes of computational problems.
- 3. explain With relevant examples and algorithms demonstrate partitioning, floor planning, area routing, clock routing and pin assignment of physical design flow

#### **Expected Course Outcome :**

At the end of the course students will be able to

- 1. Formulate the graphs for the given problems;
- 2. Calculate and analyse the computational complexity of physical design algorithms;
- 3. Partition a given design.
- 4. Express and change the floorplans in an abstract manner and use computer algorithms to make large and optimized floorplans
- 5. Make optimized placements on the silicon chip and perform complex routing using algorithms and computer codes.
- 6. Design clock trees to distribute the clock signals on the chip while satisfying various constraints like clock skew and wire length.

## Module:1 Introduction to course

Y Chart- Physical design top down flow- Review of graph theory: complete graph, connected graph, sub graph, isomorphism, bi partite graph tree.

## Module:2 | Computational complexity of algorithms

Big-O notation- Class P- class NP -NP-hard- NP-complete.

## Module:3 | Partitioning

Problem formulation- Group Migration Algorithm: Kernighan-Lin Simulated annealing based Partitioning.

## Module:4 | Floor planning

Stock Meyer algorithm- Wong-Liu algorithm (Normalized polish expression)- Integer Linear Programming (ILP) based floor planning.

## Module:5 | Pin Assignment and Placement

Pin Assignment: Concentric circle mapping, Topological pin assignment- Power and ground routing.

Placement: Wire length estimation models for placement - Quadratic placement- Sequence pair technique.

Module:6 | Routing

8hours

6 hours

7 hours

5 hours

4 hours

Routing: Grid routing- Maze routing- Line Probe algorithms, Weighted Steiner tree approach. Global routing: Rectilinear routing(spanning tree, steiner tree)-Dijkstra's algorithm-routing by ILP Detailed routing: Problem formulation- Two layer channel routing : Left Edge algorithm, Dogleg router- Net Merge channel router - Three-layer channel routing - HVH, VHV router- Introduction to switch box routing.

## Module:7 Clocking Tree Topologies

7hours

Clocking tree topologies: H-tree, Xtree- Method of Means and Medians (MMM)- recursive geometric matching- Elmore delay model to calculate skew- Buffer insertion in clock trees- Exact Zero skew clock routing algorithm. Clock mesh topologies: uniform and non-uniform mesh.

Module:8Contemporary issues:2he		2hours					
			Total	Lecture hours:	45hours		
Tex	<mark>xt Book</mark> (	s)					
1.	Andrew	B. Kahng, Jens Lienig,	Igor L. Markov, JinHu,VLSI I	Physical Design:	From Graph		
	Partitio	ning to Timing Closure, S	Springer, 2011.				
2	H. Yos	suff and S.M. Sait, VI	SI Physical Design Automat	ion – Theory a	and Practice,		
	Cambri	dge India, 2010.					
3.	Sung K	Kyu Lim, Practical Probl	ems in VLSI Physical Design	Automation, Sp	ringer India,		
	2011.						
Ref	erence l	Books					
1.	S. Sridl	har, Design and Analysis	of Algorithms, Paperback – OU	P, 2014.			
2.	John C	kyereAttia, PSPICE and	I MATLAB for Electronics: A	An Integrated Ap	pproach,CRC		
	Press, 2	2010.					
3.	Ganesh	M.Magar, Swati R.M	aurya Rajesh K.Maurya, Gra	ph Theory &	Applications,		
	Technie	cal Publications, 2016.					
4	Brian C	Christian and Tom Griffith	ns, Algorithms to Live By: The	Computer Scien	ce of Human		
	Decisio	ns, William Collins, 2017	7.				
Mo	de of Ev	valuation:Continuous Ass	essment Test -I (CAT-I), Con	ntinuous Assessn	nent Test -II		
(CA	(CAT-II), Seminar / Challenging Assignments / Completion of MOOC / Innovative ideas leading						
to s	olutions	for industrial problems, F	Final Assessment Test (FAT).				
Rec	comment	led by Board of Studies	13-12-2015				
App	proved b	y Academic Council	No. 40	18-03-2016			

Course Code	Course Title	ΓΡJC						
ECE5020	DSP ARCHITECTURES 2 0	0 4 3						
Pre-requisite	Nil							
Course Objectives								
The course is aimed to								
-	ferent Digital Signal Processor (DSP) architectures and to design systematic DSPs	ems using						
programma 2 Improve sv	ystem performance using different pipelining techniques, processor	array and						
systolic arra		anay and						
•	f memory and peripherals to a DSP; and acquire knowledge on differ	rent codec						
implemente								
<b>Expected Course</b>								
The students will b	be able to							
1. Identify and	d use specific Digital Signal Processor for various applications.							
-	/stem using programmable DSP.							
	pipelining techniques to improve system performance.							
	applications using processor array and systolic arrays to enh	nance the						
performanc								
	olving memory and other interfaces to DSP.							
6. Design of v	various codecs on target DSPs.							
		21						
	Integrated Circuits and VLSI Technologies	2hours						
	ignal processors - Application specific IC's for DSP - DSP systemetry begrated circuit design.	ins - DSP						
system design - m	egrated circuit design.							
Module:2 Archi	itectures for programmable DSP	4 hours						
	al Features - DSP Computational Building Blocks - Bus Archite							
Memory - Data	Addressing Capabilities - Address Generation Unit - Programmal							
Program Execution	n - Features for External Interfacing.							
	ution Control and Pipelining	4 hours						
	– Interrupts – Stacks - Relative Branch support - Pipelining and Perf Interlocking - Branching effects - Interrupt effects - Pipeline Prog							
models.	interlocking - Dranching effects - Interrupt effects - Tipeline Trog	grammig						
models.								
Module:4 Synth	nesis of DSP Architectures	6 hours						
	ach to DSP LSI - Circuit Synthesis - High Performance Data c							
Techniques - LSI Algorithms and Architectures - Hierarchical Design of Processor Arrays -								
Systolic Arrays - S	tack Filters - Wave-front Array Processors.							
	facing Memory and I/O to DSP Processors	5 hours						
	facing signals - Memory interface - Parallel I/O interface - Programme							
McBSP Program	O-Direct memory access (DMA) A Multichannel buffered serial port (I ning.	wichor) -						
	<u></u> <i>o</i> .							
Module:6 Inter	facing CODEC	3 hours						
	circuit - CODEC programming - A CODEC-DSP interface example.							

Module:7	Multiprocessor Systems	4hours
Architecture	s of Multiprocessors-Performance comparison of -Multiprocessor Structures.	
Module:8	Contemporary issues:	2hours
	Total Lecture hours:	30hours
Text Book		
	Vanhammer, DSP Integrated Circuits, Academic press, New York, 2011.	
	Singh and S. Srinivasan, Digital Signal Processing, Thomson Publications, 20	012.
Reference		
	apsley, Jeff Bier, AmitShoham, Edward A. Lee, DSP Processor Fun ectures & Features, Wiley-IEEE Press, First Edition, 2011.	damentals.
	Pirsch, Architectures for Digital signal processing, Wiley India, 2010.	
Mode of E (CAT-II), S	valuation: Continuous Assessment Test –I (CAT-I), Continuous Assessment Seminar / Challenging Assignments / Completion of MOOC / Innovative ide for industrial problems, Final Assessment Test (FAT).	
	jects (Indicative)	
<ol> <li>Ima</li> <li>Turi</li> <li>COI</li> <li>Imp</li> </ol>	ge Compression algorithm implementation in Programmable DSP. ge processing algorithm implementations on FPGA. bo Decoder implementation. RDIC Algorithm implementation in PDSP/FPGA/ASIC flow. roved Adaptive filters. roved Median filters.	
-	valuation: Review I, II and III	
	ded by Boord of Studiog 12 12 2015	

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Recommended by Board of Studies	13-12-2015	
Approved by Academic Council	No. 40	18-03-2016

<b>Course Code</b>	Course Title	L	Τ	P	J	С
ECE5022	VLSI DIGITAL SIGNAL PROCESSING	3	0	0	0	3
Pre-requisite	Nil					

#### **Course Objective :**

The course aimed to:

- 1. Familiarise various representation methods of DSP algorithms, understand the significance of the iteration bound and to calculate the same for a given single-rate and/or multi-rate DFG.
- 2. Understand and apply the architectural transformation techniques such as retiming, unfolding and folding on a given DFG.
- 3. Introduce the algorithmic and numerical strength reduction methods for performance improvement.
- 4. Signify and calculate the effects of scaling and round-off noise for a given digital filter with limited word length.

#### **Expected Course Outcome :**

The students will be able to:

- 1. Compare various representation methods of DSP algorithms.
- 2. Find iteration bound of a given single and/or multi-rate DFG.
- 3. Understand and transform the given DFG using retiming with constraints.
- 4. Apply unfolding and folding transformations on the given DFG.
- 5. Understand and apply algorithmic and numerical strength reduction methods.
- 6. Understand and calculate scaling and round-off noise of the given digital filter with limited word length.

#### Module:1 Introduction to Digital Signal Processing

Typical DSP Algorithms - DSP Application Demands and Scaled CMOS Technologies -Representations of DSP Algorithms - Data-Flow Graph Representations.

#### Module:2 | Iteration Bound

Introduction - Loop Bound and Iteration Bound - Algorithms for Computing Iteration Bound: Longest Path Matrix and Multiple Cycle Mean algorithms - Iteration Bound of Multi-rate Data Flow Graphs.

#### Module:3 | Pipelining, Parallel processing and Retiming

Pipelining and Parallel Processing - Introduction to Retiming - Definitions and Properties -Solving Systems of Inequalities - The Bellman-Ford Algorithm - The Floyd Warshall Algorithm-Retiming Techniques.

#### Module:4 Unfolding

Introduction, An Algorithm for Unfolding, Properties of Unfolding, Critical Path, Unfolding, and Retiming, Applications of Unfolding.

#### Module:5 | Folding

Introduction, Folding Transformation, Register Minimization Techniques, Register Minimization in Folded Architectures.

Module:6 | Algorithmic & Numerical Strength Reduction 7 hours Introduction to Algorithmic Strength Reduction, Cook-Toom Algorithm, Iterated Convolution, Cyclic Convolution, Discrete Cosine Transform. Introduction to Numerical Strength

5 hours

5 hours

8 hours

6 hours

Reduction, Canonic Signed Digit Arithmetic, Sub-expression Elimination, Multiple Constant Multiplication, Sub-expression Sharing in Digital Filters.

## Module:7 Scaling and Rounding Noise

6 hours

Introduction, Scaling and Rounding Noise, State Variable Description of Digital Filters, Scaling and Rounding Noise Computation, Rounding Noise in Pipelined IIR Filters.

## Module:8 Contemporary issues:

			<b>Total Lecture:</b>	45 hours		
Tex	kt Book(s)					
1.	, <b>C</b>	Signal Processing	Systems: Des	sign and		
	Implementation, Reprint, Wiley, Inter So	cience, 2014.				
Ref	ference Books					
1.	John G. Proakis, Dimitris K Manolak	tis, Digital Signal Pro	cessing: Principles	s, Algorithms		
	and Applications, Prentice Hall, Fourth	Edition, 2015.				
2.	Mohammed Ismail and Terri Fiez, Ana	alog VLSI Signal and I	Information Proces	ssing,McGraw-		
	Hill, 2014.					
3.	S.Y. Kung, H.J. White House, T. Kaila	th, VLSI and Modern S	Signal Processing,	PHI, 2010.		
4.	S. K. Mitra, Digital Signal Processir	ng – A Computer Ba	sed Approach, Fo	ourth Edition,		
	McGraw-Hill, 2010.					
Mo	de of Evaluation:Continuous Assessme	nt Test –I (CAT-I), C	Continuous Assess	ment Test –II		
(CAT-II), Seminar / Challenging Assignments / Completion of MOOC / Innovative ideas leading						
to solutions for industrial problems, Final Assessment Test (FAT).						
Rec	commended by Board of Studies	13-12-2015				
App	proved by Academic Council	No. 40	18-03-2016			

Course Code	Course Title	L T P J C
ECE5023	MEMORY DESIGN AND TESTING	3 0 0 0 3
Pre-requisite	Nil	

#### **Course Objectives :**

The course is aimed at

- 1. Expounding the basics and detailed architecture of SRAMs and DRAMs.
- 2. model the memory fault and introduce the basic and advanced memory testing patterns.
- 3. Elaborate the reliability and radiation effect issues of semiconductor memories and present methods for radiation hardening.
- 4. Review and discuss high performance memory subsystems, advanced memory technologies and contemporary issues

#### **Expected Course Outcome :**

At the end of the course the student should be able to

- 1. Design SRAMs and DRAMs.
- 2. Design NVRAMs and Flash Memories.
- 3. Model memory faults, select suitable testing patterns and develop testing patterns.
- 4. Incorporate DFT and BIST techniques for semiconductor memory testing.
- 5. Improve the reliability of semiconductor memories, simulate and model radiation effects and, perform radiation hardening.
- 6. Contribute to the development of high performance memory subsystems and use advanced memory technologies.

#### Module:1 Volatile memories

SRAM - SRAM Cell structures, MOS SRAM Architecture, MOS SRAM cell and peripheral circuit operation, SOI technology, Advanced SRAM architectures and technologies, soft error failure in SRAM, Application specific SRAMs, DRAM - DRAM technology development, CMOS DRAM, DRAM cell theory and advanced cell structures, BICMOS DRAM, soft error failure in DRAM, Advanced DRAM design and architecture, Application specific DRAM.

#### Module:2 Non-volatile memories

Masked ROMs, High density ROM, PROM, Bipolar ROM, CMOS PROMS, EPROM, Floating gate EPROM cell, One time programmable EPROM, EEPROM, EEPROM technology and architecture, Non-volatile SRAM, Flash Memories (EPROM or EEPROM), advanced Flash memory architecture.

#### Module:3 | Memory Testing and Patterns

General Fault Modeling – Read Disturb Fault Model – Precharge Faults – False Write Through Data Retention Faults – Decoder Faults. Megabit DRAM Testing Nonvolatile Memory Modeling and Testing-IDDQ Fault Modeling and Testing Application Specific Memory Testing – Zero/one Pattern – Exhaustive Test Patterns – Walking, Matching and Galloping – Pseudo Random Pattern – CAM pattern.

## Module:4 Design For Test and BIST

RAM Built-In Self – Test (BIST)-Weak Write Test mode – Bit Line Contact Resistance – PFET Test – Shadow Write and Shadow Read.

#### Module:5 | Reliability and Radiation Effects

7 hours

4hours

5 hours

7 hours

General Reliability Issues-RAM Failure Modes and Mechanism-Nonvolatile Memory Reliability-Design for Reliability Radiation Effects-Single Event Phenomenon (SEP)- Radiation Hardening Techniques Radiation Hardening Process and Design Issues-Radiation Hardened Memory Characteristics.

#### Module:6 | High-Performance Subsystem Memories 7 hours Hierarchical Memory Systems, Memory-Subsystem Technologies, High-Performance Standard DRAMs, Embedded Memories.

Module:7 Advanced Memory Technologies 8 hours High-Density Memory Packaging Technologies, Ferroelectric Random Access Memories (FRAMs)- Analog Memories-Magneto-resistive Random Access Memories (MRAMs)-Experimental Memory Devices Memory Hybrids and MCMs (2D)- Memory Stacks and MCMs (3D)-Memory MCM Testing and Reliability. Module:8 | Contemporary issues: 2 hours Total Lecture hours: 45 hours Text Book(s) 1. A. K.Sharma, Advanced Semiconductor Memories: Architecture, Design and Applications, John Wiley, 2014. 2. Roberto Gastaldi and Giovanni Campardo In Search of the Next Memory: Inside the Circuitry from the Oldest to the Emerging Non-Volatile Memories, Springer, 2017. **Reference Books** Alberto Bosio, Luigi Dilillo, Patrick Girard, Serge Pravossoudovitch, Arnaud Virazel, 1. Advanced Test Methods for SRAMs: Effective Solutions for Dynamic Fault Detection in Nanoscaled Technologies, Springer, 2010. Hao Yu and YuhaoWang, Design Exploration of Emerging Nano-scale Non-volatile Memory, 2. Springer, 2014. Takayuki Kawahara (Editor), Hiroyuki Mizuno (Editor), Green Computing with Emerging 3. Memory: Low-Power Computation for Social Innovation, Springer, 2012. Mode of Evaluation: Continuous Assessment Test -I (CAT-I), Continuous Assessment Test -II (CAT-II), Seminar / Challenging Assignments / Completion of MOOC / Innovative ideas leading to solutions for industrial problems, Final Assessment Test (FAT).

to solutions for madistrial problems, i mai rissessment rest (1111).					
Recommended by Board of Studies	13-12-2015				
Approved by Academic Council	No. 40	18-03-2016			

Course Code	Course Title	L T P J C
ECE5024	IC TECHNOLOGY	3 0 0 0 3
Pre-requisite	Nil	

#### **Course Objective :**

The course is aimed to

- 1. Introduce the process involved in semiconductor manufacturing and fabrication.
- 2. Model the oxidation growth rate & to understand oxidation process and the process of diffusion and to expound the Ion Implantation process.
- 3. Explain the thin film deposition process and review the difference between MOS and Bipolar Process Integration.

#### **Expected Course Outcome :**

At the end of the course the student will be able to

- 1. Understand the process involved in semiconductor manufacturing and fabrication.
- 2. Understand the various lithography techniques used for pattern transfer.
- 3. Model the oxidation growth.
- 4. Model the diffusion mechanism in semiconductors.
- 5. Understand the process involved in thin film deposition.
- 6. Analyse the difference between MOS and Biploar Process.

#### Module:1 Crystal Growth

Introduction to Semiconductor Manufacturing and fabrication, Clean Room types and Standards, Physics of the Crystal growth, wafer fabrication and basic properties of silicon wafers.

#### Module:2 Lithography:

The Photolithographic Process, Photomask Fabrication, Comparison between positive and negative photoresists, Exposure Systems, Characteristics of Exposure Systems, E-beam Lithography, X- ray lithography.

#### Module:3 Thermal Oxidation of Silicon:

The Oxidation Process, Modeling Oxidation, Masking Properties of Silicon Dioxide, Technology of Oxidation, Si-SiO2 Interface.

#### Module:4 Diffusion and Ion Implantation:

The Diffusion Process, Mathematical Model for Diffusion, Constant-, The Diffusion Coefficient, Successive Diffusions, Diffusion Systems, Implantation Technology, Mathematical Model for Ion Implantation, Selective Implantation, Channeling, Lattice Damage and Annealing, Shallow Implantations.

#### 7 hours

5 hours

## 6 hours

Module:5	Thin film deposition, conta	acts, packaging and yield:		7 hours
Chemical Vapor Deposition, Physical Vapor Deposition, Epitaxy, Metal Interconnections and				
Contact Technology, Silicides and Multilayer-Contact Technology, Copper Interconnects and				rconnects and
		g and Die Separation, Die	Attachment, V	Vire Bonding,
Packages,	Yield.			
-	MOS Process Integration			5 hours
		S Transistor Layout and Desig	gn Rules, Com	plementary
MOS (CM	OS) Technology.			
Module:7	Bipolar Process Integratio			6 hours
		n, Advanced Bipolar Structur		
		s, Low-Voltage/Low-Power	CMOS/BiCM	OS Processes.
Future Tren	ds and Directions of CMOS/I	BiCMOS Processes.		
Module:8	Contemporary issues:			2 hours
Module:8	Contemporary issues:			2 hours
Module:8	Contemporary issues:	Total Lee	cture hours:	2 hours 45 hours
Module:8	_ <u> </u>	Total Lee	cture hours:	
Text Book(	s)	<b>Total Lee</b> cGraw-Hill, Second Edition, 2		
<b>Text Book</b> ( 1. S.M. S	s) ze, VLSI technology, Tata M	cGraw-Hill, Second Edition, 2	2017.	45 hours
<b>Text Book</b> ( 1. S.M. S	s) ze, VLSI technology, Tata M leger, Introduction to microel		2017.	45 hours
Text Book(1.S.M. S2.R.C. JaReference	s) ze, VLSI technology, Tata M leger, Introduction to microel <b>Books</b>	cGraw-Hill, Second Edition, 2 ectronic fabrication, Prentice 1	2017. Hall, Second I	<b>45 hours</b> Edition, 2013.
Text Book(           1.         S.M. S           2.         R.C. Ja           Reference         1           1.         S.A. (	s) ze, VLSI technology, Tata M leger, Introduction to microel <b>Books</b> Campbell, The science and	CGraw-Hill, Second Edition, 2 ectronic fabrication, Prentice 1 l engineering of microelect	2017. Hall, Second I	<b>45 hours</b> Edition, 2013.
Text Book(           1.         S.M. S           2.         R.C. Ja           Reference         I           1.         S.A. O           Univer         Intervention	s) ze, VLSI technology, Tata M leger, Introduction to microel <b>Books</b> Campbell, The science and sity Press, UK, Second Editio	CGraw-Hill, Second Edition, 2 ectronic fabrication, Prentice 1 l engineering of microelect	2017. Hall, Second I ronics fabric	<b>45 hours</b> Edition, 2013. ation, Oxford
Text Book(           1.         S.M. S           2.         R.C. Ja           Reference         1           1.         S.A. C           Univer         2.           2.         Simon	s) ze, VLSI technology, Tata M leger, Introduction to microel Books Campbell, The science and sity Press, UK, Second Edition M. Sze, Gary S. May Fundan	CGraw-Hill, Second Edition, 2 ectronic fabrication, Prentice 1 d engineering of microelect on, 2012. nentals of Semiconductor Fabr	2017. Hall, Second I ronics fabric rication, Wile	45 hours Edition, 2013. ation, Oxford y, 2011.
Text Book(         1.       S.M. S         2.       R.C. Ja         Reference 1         1.       S.A. C         Univer       2.         Simon       Mode of E <sup>4</sup>	s) ze, VLSI technology, Tata M leger, Introduction to microel Books Campbell, The science and sity Press, UK, Second Edition M. Sze, Gary S. May Fundan valuation: Continuous Assess	CGraw-Hill, Second Edition, 2 ectronic fabrication, Prentice 1 d engineering of microelect on, 2012. nentals of Semiconductor Fabr sment Test –I (CAT-I), Cont	2017. Hall, Second I ronics fabric rication, Wile inuous Assess	45 hours Edition, 2013. ation, Oxford y, 2011. sment Test –II
Text Book(         1.       S.M. S         2.       R.C. Ja         Reference 1         1.       S.A. C         Univer       2.         Simon       Mode of Ev         (CAT-II), S	s) ze, VLSI technology, Tata M leger, Introduction to microel Books Campbell, The science and sity Press, UK, Second Editio M. Sze, Gary S. May Fundan valuation: Continuous Assess Jeminar / Challenging Assign	CGraw-Hill, Second Edition, 2 ectronic fabrication, Prentice I d engineering of microelect on, 2012. nentals of Semiconductor Fabr sment Test –I (CAT-I), Cont uments / Completion of MOO	2017. Hall, Second I ronics fabric rication, Wile inuous Assess	45 hours Edition, 2013. ation, Oxford y, 2011. sment Test –II
Text Book(         1.       S.M. S         2.       R.C. Ja         Reference I         1.       S.A. C         Univer       Univer         2.       Simon         Mode of Ev       (CAT-II), S         to solutions       Solutions	s) ze, VLSI technology, Tata M leger, Introduction to microel Books Campbell, The science and sity Press, UK, Second Edition M. Sze, Gary S. May Fundan valuation: Continuous Assess	CGraw-Hill, Second Edition, 2 ectronic fabrication, Prentice I d engineering of microelect on, 2012. nentals of Semiconductor Fabr sment Test –I (CAT-I), Cont uments / Completion of MOO	2017. Hall, Second I ronics fabric rication, Wile inuous Assess	45 hours Edition, 2013. ation, Oxford y, 2011. sment Test –II

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Recommended by Board of Studies	13-12-2015	
Approved by Academic Council	No. 40	18-03-2016

Course Code	Course Title L	T P J C
ECE5025	SYSTEM ON CHIP DESIGN 3	0 0 0 3
Pre-requisite	Nil	
<b>Course Objectiv</b>	7e :	
The course is ain		
1. Introduc	cing design, optimization, and programing a modern System-on-a-Chi	p.
	g SoC design with on-chip memories and communication networks, I/	
interfac	ing.	
3. Making	them understand about signal integrity aware SoC design and Schedul	ling
algorith	ms.	
<b>Expected Cours</b>		
	course the student will be able to	
	rate an ability to identify, formulate and treat complex issues in the	field of
	n-chip from a holistic perspective.	
-	he performance of SoC based design by various advanced techniques.	
	stemC for system design.	
	connection structures in a SoC / NoC based system design.	
	tic timing analysis for a SoC based design.	hulin a
6. Analyse t	he cause and eliminate the issues relevant to signal integrity and sched	lunng.
Module:1 Intr	roduction	2 h a
		3 hours
Libraries – EDA	ne present-day SoC - Design issues of SoC- Hardware-Software Co de	sign – Core
Libraries – EDA	10018.	
Module 2 Des	ign Methodology for Logic Memory and Analog Cores	6 hours
	ign Methodology for Logic, Memory and Analog Cores	6 hours
SoC Design Flov	v – guidelines for design reuse – Introduction- Efficiency of application	n specific
SoC Design Flow hardware- Target	v – guidelines for design reuse – Introduction- Efficiency of application architectures for HW/SW partitioning -System Integration, Embedded	n specific
SoC Design Flow hardware- Target	v – guidelines for design reuse – Introduction- Efficiency of application	n specific
SoC Design Flow hardware- Target – design methodo	v – guidelines for design reuse – Introduction- Efficiency of application architectures for HW/SW partitioning -System Integration, Embedded plogy for embedded memories – Specification of analog cores.	n specific d memories
SoC Design Flow hardware-Target – design methodo Module:3 Intr	v – guidelines for design reuse – Introduction- Efficiency of application architectures for HW/SW partitioning -System Integration, Embedded	n specific d memories 7 hours
SoC Design Flow hardware- Target – design methodo Module:3 Intr Co-Specification	y – guidelines for design reuse – Introduction- Efficiency of application architectures for HW/SW partitioning -System Integration, Embedded blogy for embedded memories – Specification of analog cores.	n specific d memories 7 hours
SoC Design Flow hardware- Target – design methodo Module:3 Intr Co-Specification	<ul> <li>y – guidelines for design reuse – Introduction- Efficiency of application architectures for HW/SW partitioning -System Integration, Embedded blogy for embedded memories – Specification of analog cores.</li> <li>roduction to System C for SoC Design</li> <li>System Partitioning- Co-simulation, Co-synthesis &amp; Co-verification</li> </ul>	n specific d memories 7 hours
SoC Design Flow hardware- Target – design methodo Module:3 Intr Co-Specification and Co-specifica	<ul> <li>y – guidelines for design reuse – Introduction- Efficiency of application architectures for HW/SW partitioning -System Integration, Embedded blogy for embedded memories – Specification of analog cores.</li> <li>roduction to System C for SoC Design</li> <li>System Partitioning- Co-simulation, Co-synthesis &amp; Co-verification</li> </ul>	n specific d memories <b>7 hours</b>
SoC Design Flow hardware-Target – design methodo Module:3 Intr Co-Specification and Co-specifica Module:4 SoC	<ul> <li>y – guidelines for design reuse – Introduction- Efficiency of application architectures for HW/SW partitioning -System Integration, Embedded ology for embedded memories – Specification of analog cores.</li> <li>roduction to System C for SoC Design</li> <li>- System Partitioning- Co-simulation, Co-synthesis &amp; Co-verification tion and Co-simulation.</li> <li>C and NoC Interconnection Structures</li> </ul>	n specific d memories 7 hours n –SystemC 7 hours
SoC Design Flow hardware-Target – design methodo Module:3 Intr Co-Specification and Co-specifica Module:4 SoC SoC Interconnect	<ul> <li>y – guidelines for design reuse – Introduction- Efficiency of application architectures for HW/SW partitioning -System Integration, Embedded blogy for embedded memories – Specification of analog cores.</li> <li>roduction to System C for SoC Design</li> <li>- System Partitioning- Co-simulation, Co-synthesis &amp; Co-verification tion and Co-simulation.</li> <li>C and NoC Interconnection Structures</li> <li>ction Structures- Bus-based Structures- AMBA Bus.Network on the system of the system o</li></ul>	n specific d memories 7 hours n –SystemC 7 hours Chip -NoC
SoC Design Flow hardware-Target – design methodo Module:3 Intr Co-Specification and Co-specifica Module:4 SoC SoC Interconnec Interconnection	<ul> <li>y – guidelines for design reuse – Introduction- Efficiency of application architectures for HW/SW partitioning -System Integration, Embedded ology for embedded memories – Specification of analog cores.</li> <li>coduction to System C for SoC Design</li> <li>- System Partitioning- Co-simulation, Co-synthesis &amp; Co-verification tion and Co-simulation.</li> <li>C and NoC Interconnection Structures</li> <li>ction Structures- Bus-based Structures- AMBA Bus.Network on Structures-Topologies- routing- flow control- network components(ro</li> </ul>	n specific d memories 7 hours n –SystemC 7 hours Chip -NoC
SoC Design Flow hardware-Target – design methodo Module:3 Intr Co-Specification and Co-specifica Module:4 SoC SoC Interconnect	<ul> <li>y – guidelines for design reuse – Introduction- Efficiency of application architectures for HW/SW partitioning -System Integration, Embedded ology for embedded memories – Specification of analog cores.</li> <li>coduction to System C for SoC Design</li> <li>- System Partitioning- Co-simulation, Co-synthesis &amp; Co-verification tion and Co-simulation.</li> <li>C and NoC Interconnection Structures</li> <li>ction Structures- Bus-based Structures- AMBA Bus.Network on Structures-Topologies- routing- flow control- network components(ro</li> </ul>	n specific d memories 7 hours n –SystemC 7 hours Chip -NoC
SoC Design Flow hardware-Target – design methodo Module:3 Intr Co-Specification and Co-specifica Module:4 SoC SoC Interconnect Interconnection S network interface	<ul> <li>y – guidelines for design reuse – Introduction- Efficiency of application architectures for HW/SW partitioning -System Integration, Embedded ology for embedded memories – Specification of analog cores.</li> <li>coduction to System C for SoC Design</li> <li>- System Partitioning- Co-simulation, Co-synthesis &amp; Co-verification tion and Co-simulation.</li> <li>C and NoC Interconnection Structures</li> <li>ction Structures- Bus-based Structures- AMBA Bus.Network on G Structures-Topologies- routing- flow control- network components(ro e, Links).</li> </ul>	n specific d memories 7 hours n –SystemC 7 hours Chip -NoC outer/switch,
SoC Design Flow hardware-Target – design methodo Module:3 Intr Co-Specification and Co-specifica Module:4 SoC SoC Interconnec Interconnection S network interface	<ul> <li>y – guidelines for design reuse – Introduction- Efficiency of application architectures for HW/SW partitioning -System Integration, Embedded ology for embedded memories – Specification of analog cores.</li> <li>coduction to System C for SoC Design</li> <li>- System Partitioning- Co-simulation, Co-synthesis &amp; Co-verification tion and Co-simulation.</li> <li>C and NoC Interconnection Structures</li> <li>ction Structures- Bus-based Structures- AMBA Bus.Network on Structures-Topologies- routing- flow control- network components(ro e, Links).</li> <li>A for SoC Design</li> </ul>	n specific d memories 7 hours n –SystemC 7 hours Chip -NoC outer/switch, 7 hours
SoC Design Flow hardware-Target – design methodo Module:3 Intr Co-Specification and Co-specification and Co-specification SoC Interconnection Interconnection network interface Module:5 STA	<ul> <li>y – guidelines for design reuse – Introduction- Efficiency of application architectures for HW/SW partitioning -System Integration, Embedded bology for embedded memories – Specification of analog cores.</li> <li>roduction to System C for SoC Design <ul> <li>System Partitioning- Co-simulation, Co-synthesis &amp; Co-verification and Co-simulation.</li> </ul> </li> <li>C and NoC Interconnection Structures <ul> <li>ction Structures- Bus-based Structures- AMBA Bus.Network on Structures-Topologies- routing- flow control- network components(roe, Links).</li> </ul> </li> <li>A for SoC Design <ul> <li>d its Timing Optimization- Slow to High and High to low frequency to the structure of the structur</li></ul></li></ul>	n specific d memories 7 hours n –SystemC 7 hours Chip -NoC outer/switch, 7 hours iming path-
SoC Design Flow hardware-Target – design methodo Module:3 Intr Co-Specification and Co-specifica Module:4 SoC SoC Interconnection Interconnection S network interface Module:5 STA Timing paths and Half cycle timing	<ul> <li>y – guidelines for design reuse – Introduction- Efficiency of application architectures for HW/SW partitioning -System Integration, Embedded ology for embedded memories – Specification of analog cores.</li> <li>coduction to System C for SoC Design</li> <li>- System Partitioning- Co-simulation, Co-synthesis &amp; Co-verification tion and Co-simulation.</li> <li>C and NoC Interconnection Structures</li> <li>ction Structures- Bus-based Structures- AMBA Bus.Network on Structures-Topologies- routing- flow control- network components(ro e, Links).</li> <li>A for SoC Design</li> </ul>	n specific d memories 7 hours n –SystemC 7 hours Chip -NoC outer/switch, 7 hours iming path-
SoC Design Flow hardware-Target – design methodo Module:3 Intr Co-Specification and Co-specification and Co-specification SoC Interconnection Interconnection network interface Module:5 STA	<ul> <li>y – guidelines for design reuse – Introduction- Efficiency of application architectures for HW/SW partitioning -System Integration, Embedded bology for embedded memories – Specification of analog cores.</li> <li>roduction to System C for SoC Design <ul> <li>System Partitioning- Co-simulation, Co-synthesis &amp; Co-verification and Co-simulation.</li> </ul> </li> <li>C and NoC Interconnection Structures <ul> <li>ction Structures- Bus-based Structures- AMBA Bus.Network on Structures-Topologies- routing- flow control- network components(roe, Links).</li> </ul> </li> <li>A for SoC Design <ul> <li>d its Timing Optimization- Slow to High and High to low frequency to the structure of the structur</li></ul></li></ul>	n specific d memories 7 hours n –SystemC 7 hours Chip -NoC outer/switch, 7 hours iming path-
SoC Design Flow         hardware-Target         - design methodo         Module:3       Intr         Co-Specification         and Co-specification         and Co-specification         Module:4       SoC         SoC Interconnection S         Interconnection S         network interface         Module:5       STA         Timing paths and         Half cycle timing         design.	<ul> <li>w – guidelines for design reuse – Introduction- Efficiency of application architectures for HW/SW partitioning -System Integration, Embedded bology for embedded memories – Specification of analog cores.</li> <li>roduction to System C for SoC Design <ul> <li>System Partitioning- Co-simulation, Co-synthesis &amp; Co-verification and Co-simulation.</li> </ul> </li> <li>C and NoC Interconnection Structures <ul> <li>ction Structures- Bus-based Structures- AMBA Bus.Network on Structures-Topologies- routing- flow control- network components(roe, Links).</li> </ul> </li> <li>A for SoC Design <ul> <li>d its Timing Optimization- Slow to High and High to low frequency to gpath- Latch time borrowing- Interface Logic Model design and analy</li> </ul> </li> </ul>	n specific d memories 7 hours n –SystemC 7 hours Chip -NoC outer/switch, 7 hours iming path- ysis for SoC
SoC Design Flow         hardware-Target         design methodo         Module:3       Intr         Co-Specification         and Co-specification         and Co-specification         and Co-specification         Module:4       SoC         SoC Interconnections         Interconnection S         network interface         Module:5       STA         Timing paths and         Half cycle timing         design.	<ul> <li>y – guidelines for design reuse – Introduction- Efficiency of application architectures for HW/SW partitioning -System Integration, Embedded bology for embedded memories – Specification of analog cores.</li> <li>coduction to System C for SoC Design <ul> <li>System Partitioning- Co-simulation, Co-synthesis &amp; Co-verification and Co-simulation.</li> </ul> </li> <li>C and NoC Interconnection Structures <ul> <li>ction Structures- Bus-based Structures- AMBA Bus.Network on Structures-Topologies- routing- flow control- network components(roe, Links).</li> </ul> </li> <li>A for SoC Design <ul> <li>d its Timing Optimization- Slow to High and High to low frequency t g path- Latch time borrowing- Interface Logic Model design and analy</li> </ul> </li> </ul>	n specific d memories 7 hours n –SystemC 7 hours Chip -NoC outer/switch, 7 hours iming path- ysis for SoC 7 hours
SoC Design Flow         hardware-Target         – design methodo         Module:3       Intr         Co-Specification         and Co-specification         and Co-specification         and Co-specification         SoC Interconnect         Interconnection S         network interface         Module:5       STA         Timing paths and         Half cycle timing         design.         Module:6       Signal Integrity	<ul> <li>w – guidelines for design reuse – Introduction- Efficiency of application architectures for HW/SW partitioning -System Integration, Embedded bology for embedded memories – Specification of analog cores.</li> <li>roduction to System C for SoC Design <ul> <li>System Partitioning- Co-simulation, Co-synthesis &amp; Co-verification and Co-simulation.</li> </ul> </li> <li>C and NoC Interconnection Structures <ul> <li>ction Structures- Bus-based Structures- AMBA Bus.Network on Structures-Topologies- routing- flow control- network components(roe, Links).</li> </ul> </li> <li>A for SoC Design <ul> <li>d its Timing Optimization- Slow to High and High to low frequency to gpath- Latch time borrowing- Interface Logic Model design and analy</li> </ul> </li> </ul>	n specific d memories 7 hours n –SystemC 7 hours Chip -NoC outer/switch, 7 hours iming path- ysis for SoC 7 hours ESD and its

Glitch analysis-Types of Glitches- Glitch Threshold and propagation- Noise Accumulation with Multiple aggressor- Aggressor timing correlation- Crosstalk Delay analysis -Timing Verification using crosstalk delay-Positive and Negative crosstalk- aggressor victim timing correlationaggressor victim functional correlation.

#### Module:7 Scheduling

6 hours

Introduction and need for HLS- Major steps-Scheduling and Allocation- Binding/Assignment-Concept of Scheduling, Heuristic Scheduling Algorithm.

Module:8	Contemporary issues:
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2 hours

Total Lecture hours:45 hours

- Text Book(s)

   1.
   Michael J. Flynn, Wayne Luk, Computer System Design: System on chip, Wiley-Blackwell, First Edition, 2011.
- J. Bhasker, RakeshChadha,STA for Nanometer design A practical approach, Springer, First Edition, 2010.

## **Reference Books**

- 1. Jose L. Ayala,Communication Architectures for Systems-on-Chip, CRC Press, First Edition, 2011.
- 2. Laung-Terng Wang, Charles E. Stroud, Nur A. Touba, System-on-Chip Test Architectures: Nanometer Design for Testability, Morgan Kaufmann, First Edition, 2010.
- 3. Ahmed Jerraya and Wayne Wolf, Multiprocessor Systems-on-Chips (Systems on Silicon Series), Morgan Kaufmann, First Edition, 2010.

Mode of Evaluation:Continuous Assessment Test –I (CAT-I), Continuous Assessment Test –II (CAT-II), Seminar / Challenging Assignments / Completion of MOOC / Innovative ideas leading to solutions for industrial problems, Final Assessment Test (FAT).

Recommended by Board of Studies	13-12-2015	
Approved by Academic Council	No. 40	18-03-2016

ECE5026	Course Title	L T P J C
Duono contrate		2 0 0 4 3
Prerequisite	Nil	
~ ~ ~ ~ ~ ~ ~ ~ ~ ~ ~ ~ ~ ~ ~ ~ ~ ~ ~ ~		
Course Object		
	is aimed to	
	the fundamental concepts of C language.	
	d the architecture of NIOS II soft core processor and the vario	ous peripheral
	es used for system design.	
	ent the interconnect fabrics for the system and to design the system u	using NIOS I
Soft cor	re Processor.	
<b>Expected</b> Cou	rse Outcome :	
-	on of the course the student will be able to:	
1. Unders	and the concepts of C language.	
2. Unders	and the NIOS II soft core processor architecture.	
3. Interpre	t the usage of various peripheral interfaces for system design.	
	o system by choosing suitable interconnect fabrics.	
5. Design	the system using NIOS II soft core processor.	
	he system by using IP block.	
7. Design	and develop embedded synthesis using FPGA.	
Module:1 B	asic C Concepts	5 hours
	structures, pointers, functions, linked list	
Module:2 Se	oft Core Processor	5 hours
Nios II Process	or - Configurability Features - Processor Architecture-Instruction set	
Module:3 P	eripheral Interfaces	5 hours
LCD, PS2, RS	232, SDRAM, SRAM Controller, VGA, Audio and Video, PIO, Extern	nal Bus bridge
and IrDA		-
Module:4 N	IOS II programming for peripheral Interfaces	4 hours
	232, SDRAM, SRAM, VGA, Audio, IrDA.	•
Module:5 In	terconnect Fabrics	3 hours
Avalon Switc	h Fabric Interconnect - Implementation and Functions- Integ	rated Design
Environment		U
	vstem Design	4 hours
Module:6 S	0	
	miroller, Real Time Clock - Interlacing using FPGA: VGA, LCD, Ca	amera
	ontroller, Real Time Clock - Interfacing using FPGA: VGA, , LCD, Ca	amera
Traffic light Co		
Traffic light Co	P Block Implementation	
Traffic light Co		
Traffic light Co Module:7 II Edge detection	<b>P Block Implementation</b> algorithm, Colour and Brightness Enhancement algorithm	2 hours
Traffic light Co Module:7 II Edge detection	P Block Implementation	2 hours
Traffic light Co Module:7 II Edge detection	<b>P Block Implementation</b> algorithm, Colour and Brightness Enhancement algorithm	2 hours 2 hours 2 hours 30 hours

Text Book(s)

1. ZainalabedinNavabi, "Embedded Core Design with FPGAs", TATA McGraw Hill Ltd, 2011.

2. Paul J. Deitel, Harvey M. Deitel, "C: How to Program", Pearson Education, 2012

## **Reference Books**

1 NIOS II Handbook, 2014.

2 T.N.Padmanabhan,ThirupuraSundari, "Design Through VerilogHDL",Wiley Student Edition, 2010.

Mode of Evaluation:Continuous Assessment Test –I (CAT-I), Continuous Assessment Test –II (CAT-II), Seminar / Challenging Assignments / Completion of MOOC / Innovative ideas leading to solutions for industrial problems, Final Assessment Test (FAT).

## **TypicalProjects**

- 1. Implementation of edge detection algorithm
- 2. Implementation of self-guided vehicle.
- 3. Implementation of smart home system
- 4. Implementation of Health Monitoring System
- 5. Implementation of Music Synthesizer.

Mode of Evaluation: Review I,	II and III

Recommended by Board of Studies	13-12-2015	
Approved by Academic Council	No. 40	18-03-2016

Course Code		LTPJC		
ECE5027		3 0 0 0 3		
Pre-requisite	Pre-requisite Nil			
Course Objective				
Course Objective				
	d to dvanced concepts of computer architecture.			
	owledge on various interconnect topology for multiprocessor syste	em and		
	pelining techniques.			
	ling different memory hierarchy for multiprocessor and multicomp	uter systems.		
<b>Expected Course</b>	Outcomes:			
At the end of the c	ourse the student will be able to:			
	the architecture of the various multiprocessors and multicomputer	•		
	ssible parallel execution at hardware and software level.			
0 1	uired static or dynamic interconnect network for a multiprocessor s	system.		
	erent pipelining techniques to reduce computation time.			
	e various memory design for multiprocessor and multicomputer.			
6. Design sca	lable parallel architecture for multiprocessor system.			
	lel computer models	3 hours		
	omputing - Classification of parallel computers - Multipr	ocessors and		
Multicomputer - N	Iultivector and SIMD computers.			
Module:2 Prog	ram and network properties	7 hours		
	llelism - Data and resource Dependences - Hardware and software			
	ing and scheduling - Grain Size and latency - Program flow i			
	ta flow - Data flow Architectures.			
		-		
	m Interconnect Architectures	7 hours		
	s and routing - Static interconnection Networks - Dynamic in			
	rocessor system Interconnects - Hierarchical bus systems - Crossb - Multistage and combining network.	bar switch and		
multiport memory	- Multistage and combining network.			
Module:4 Pipel	ining	7 hours		
	processor - nonlinear pipeline processor - Instruction pipeli			
	nstruction pipelining - Dynamic instruction scheduling - Bran	ne Design -		
to also in an 1				
techniques - branc	h prediction - Arithmetic Pipeline Design			
	· · · · ·	nch Handling		
Module:5 Mem	ory Hierarchy Design	6 hours		
Module:5 Mem Cache basics & c	ory Hierarchy Design ache performance - reducing miss rate and miss penalty - mu	6 hours		
Module:5 Mem Cache basics & c	ory Hierarchy Design	6 hours		
Module:5 Mem Cache basics & c hierarchies - main	ory Hierarchy Design ache performance - reducing miss rate and miss penalty - mu memory organizations - design of memory hierarchies.	hch Handling 6 hours Itilevel cache		
Module:5 Mem Cache basics & c hierarchies - main	ory Hierarchy Design ache performance - reducing miss rate and miss penalty - mu	6 hours		
Module:5MemCache basics & chierarchies - mainModule:6Share	ory Hierarchy Design ache performance - reducing miss rate and miss penalty - mu memory organizations - design of memory hierarchies. ed Memory Architectures	6 hours     Itilevel cache     7 hours		
Module:5MemCache basics & chierarchies - mainModule:6Symmetric sharec	ory Hierarchy Design ache performance - reducing miss rate and miss penalty - mu memory organizations - design of memory hierarchies. ed Memory Architectures memory architectures - distributed shared memory architect	6 hours       Itilevel cache       7 hours       ures - cache		
Module:5MemCache basics & chierarchies - mainModule:6ShareSymmetric sharedcoherence protoco	ory Hierarchy Design ache performance - reducing miss rate and miss penalty - mu memory organizations - design of memory hierarchies. ed Memory Architectures	6 hours       Itilevel cache       7 hours       ures - cache		
Module:5MemCache basics & chierarchies - mainModule:6ShareSymmetric sharedcoherence protoco	ory Hierarchy Design ache performance - reducing miss rate and miss penalty - mu memory organizations - design of memory hierarchies. ed Memory Architectures memory architectures - distributed shared memory architect ls - scalable cache coherence - directory protocols - memory ba	6 hours       Itilevel cache       7 hours       ures - cache		

		nal models - An Argument for es - Benchmark Performances.	r parallel Architectures -	- Scalability	of Parallel
Мо	dule:8	Contemporary issues:			2 hours
			Total Leo	cture hours:	45 hours
Tex	xt Book(	s)			
1.		wang, NareshJotwani, Advanced nmability, Tata McGraw Hill Educ	1		•
Ref	ference I		, ,	,	
1.		. Hennessy, David A. Patterson, Kaufmann, Fifth Edition, 2011.	Computer Architecture: A	Quantitative	e Approach,
2.	2. DezsoSima, Terence Fountain, PeterrKarsuk Advanced computer Architectures – A Design Space Approach, Pearson, 2014.				
Mo	Mode of Evaluation:Continuous Assessment Test -I (CAT-I), Continuous Assessment Test -II				
	(CAT-II), Seminar / Challenging Assignments / Completion of MOOC / Innovative ideas leading				
	to solutions for industrial problems, Final Assessment Test (FAT).				
		led by Board of Studies	13-12-2015		
		y Academic Council	No. 40	18-03-2016	

Course Code	Course Title	LTPJC
ECE5028	MICROSENSORS AND INTERFACE ELECTRONICS 2	2 0 0 4 3
Pre-requisite	Nil	<u> </u>
<b>Course Objective</b>		
The course	is aimed to	
	various types of Microsensors & micro actuators corresponding mat	erials to
fabricate it		
	u Understand the concepts of Microsystem technologies used for rea	lizing
	ors and actuators.	• • •
-	e working principles of interface electronics circuits for resistive, ca	pacifive and
temperatur	e sensors.	
Exported Course	Outcome	
Expected Course	on of the course, students will be able to:	
-	d the Micro and Smart Systems.	
	EMS materials and Properties.	
•	d the fabrication process flow for Microsystems.	
	d Comprehend different types of Sensors and Actuators.	
•	out the wide applications of Microsensors.	
6. Understand	d the basic Interface Circuits.	
7. Understand	d the approach in design of Sensor Interface circuits.	
	eduction to Micro and Smart Systems	3 hours
•	scaling law, MEMS & Micro machines, Evolution of Microsystems	, Silicon and
Non-silicon Micro	and Smart Systems, Market for Microsystems.	
	osystem Materials and Properties	3 hours
PMMA, PDMS), (	n, Silicon oxide and nitride, Thin Metal films (Cr, Au, Ti, Pt), Polym	iers (SU8,
	l properties-Young modulus, Poisson's ratio, density, piezoresistive	coefficients
	nductivity, Material Structure.	coefficients,
Module:3 Micr	o System Technology	5 hours
	licon Growth, Wafer Cleaning, Oxidation, Diffusion, Ion implan	
•	ing, Lithography, Bulk Micromachining, Surface Micromachin	
Bonding and Pack	aging.	_
Module:4 Intro	eduction to Sensors and Actuators	4 hours
	coelectric, Piezoresistive, Electromagnetic, Thermo pneumatic, Sh	ape Memory
Alloy, Thermoeled	ctric, Optical and Resonant.	
<b></b>		47
	ications of Micro Devices	4 hours
	tomotive Applications: Pressure Sensors, Accelerometers, Gas Se	ensors, Flow
	es, Micro mixer, Micro Valve, Micro Pump, Micro heater.	daviasa
	on Applications: Imaging and Displays, Fiber optic communication of Systems 2 Riomadical Applications: Micro & Nano Cantilay	
	Systems -2. Biomedical Applications: Micro & Nano Cantilev	

Micro and Smart Systems -2. Biomedical Applications: Micro & Nano Cantilevers, Glucose sensors, In Vitro and In Vivo Diagnostics.RF Applications – Switches, Phase Shifters, Resonators and Varactors.

Modul	e:6 Interface Circuits			5 hours
Interfa	ace circuits for Resistive, Capa	acitive and Temperature Se	nsors	
	e:7 Voltage and Current -			4 hours
capaci Currei	ge-Mode Approach in Sensor tive sensor interfacing, temper nt-Mode Approach in Se ive/Capacitive Sensors, DC-E	cature sensor interfaces. ensor Interfaces Design	, AC-Excitation V	oltage for
Modul	e:8 Contemporary issues	:		2 hours
mouur		•		2 110415
		Т	otal Lecture hours:	30 hours
Toyt D	ook(s)			
<b>Text B</b> 1. M.	Madou, Fundamentals of N	Vicrofabrication and Nano	technology CRC Pre	se Third
	lition, 2011.		icelliology, CKC TK	.ss, 11110
	deria De Marcellis, Giusepp	e ferri. Analog circuits and	l systems for voltage-	mode and
	rrent-mode sensor interfacing	_		
	nce Books			
1. N.	Maluf, K Williams, A	An Introduction to Mi	croelectromechanical	Systems
En	gineering, Artech House Inc, S	econd Edition, 2004		-
2. S.	Senturia, Microsystem Design	n, Springer Publisher, 2007	•	
3. Mi	inhangBao, Analysis and Desi	ign Principles of MEMS De	evices, Elsevier Scienc	e, 2005.
	Kovacs, Micromachined Tran			
	of Evaluation: Continuous As			
	I), Seminar / Challenging As	0 1		deas leading
	ions for industrial problems, l	Final Assessment Test (FA	Г).	
	Projects (Indicative)		11	
	Design of Piezoelectric cantil		applications.	
	Fault detection using accelero	•••		
	Design of Silicon pressure set PDMS pressure sensor for dis			
	PDMS grippers for the micro			
	Thermoactuator switches for	1 0	cens.	
	Design of Gas sensors for aut			
	of Evaluation: Review I, II &			
		13-12-2015		
	mended by Board of Studies	13-12-2013		

<b>Course Code</b>	Course Title	L T P J C			
ECE5029VLSI TESTING AND TESTABILITY3000					
Pre-requisite	Pre-requisite Nil				
Course Objecti					
The course is					
	id simulate different types of faults in digital circuits at the gate leve	l.			
	equivalence and dominance relationships of faults in a circuit.				
_	automatic test pattern generation algorithms with respect to search erage and other criteria.	space, speed,			
	lesign complexity, ensure reliable operation, and achieve short t	time-to-market			
	ious testing methodologies.				
<b>Expected Cours</b>	se Outcome :				
After completion	n of the course students will be able to:				
1. Model di	fferent fault models.				
2. Simulate	faults and generate test patterns for combinational circuits.				
	an based testing.				
	te the BIST techniques for improving testability.				
	nd boundary scan based test architectures.				
-	and apply the test vector compression techniques for memory redu	ction and fault			
diagnosis					
	Ilt Modelling	6hours			
-	esting - Testing during the VLSI Lifecycle - Challenges in the VLS	-			
	It Models - Levels of Abstraction in VLSI Testing - Historical Re				
	y - Functional Versus Structural Testing - Levels of Fault M				
Equivalence - Fa	ult Dominance - Fault Collapsing - Check point Theorem - Delay F	ault.			
Module:2 Fai	It Simulation and Test Generation	7hours			
Fault Simulation	n: Serial, Parallel, Deductive, Concurrent - Combinational Test	Generations -			
ATPG for Com	pinational Circuits - D-Algorithm - Testability Analysis - SCOAF	' measures for			
Combinational C	Circuits				
Module:3 Sca	n based Testing	7hours			
	ability Basics - Ad Hoc Approach - Structured Approach - Scan				
_	res - Scan Design Rules - Scan Design Flow – Special Purpose S	-			
RTL Design for					
2 2 301gii 101					

## Module:4 Built-in Self-Test

BIST Design Rules - Test Pattern Generation - Exhaustive Testing - Pseudo-Random Testing -Pseudo-Exhaustive Testing - Delay Fault Testing - Output Response Analysis - Logic BIST Architectures - BIST Architectures for Circuits with and without Scan Chains

# Module:5Boundary scan and Core based Testing5hoursDigital Boundary Scan (IEEE Std. 1149.1): Test Architecture and Operations - On-Chip TestSupport with Boundary Scan - Board and System-Level Boundary-Scan Control Architectures.

Module:6	Test Compression and Com	paction		6hours
Test Stimul	is Compression: Code-Based So	chemes, Linear-Decon	pression-Based Sch	nemes - Test
Response Co	ompaction.			
Module:7	Fault Diagnosis			5hours
Dictionary E	Based and Adaptive fault diagno	sis.		
Module:8	<b>Contemporary issues:</b>			2hours
	<b>Total Lecture hours:</b>			45hours
<b>Text Book</b> (s	5)			
1. Z.Nava	bi, Digital System Test and Tes	table Design, Springer,	, 2011.	
1. Laung-	Terng Wang, Cheng-Wen W	u, and Xiaoqing We	en, VLSI Test Pri	inciples and
Archite	ctures, The Morgan Kaufmann,	2013.		-
Mode of Ev	aluation:Continuous Assessmen	nt Test –I (CAT-I), C	Continuous Assessm	ent Test –II
(CAT-II), Se	eminar / Challenging Assignme	nts / Completion of M	OOC / Innovative i	deas leading
to solutions	for industrial problems, Final As	ssessment Test (FAT).		-
	led by Board of Studies	13-12-2015		
Approved by	y Academic Council	No. 40	18-03-2016	ń

Course code	Course Title	LTPJC
ECE 5030	Scripting languages for VLSI design automation	20203
Pre-requisite	None	Syllabus version
		v. 1.0
Course Object		
The course is ai		
	scripts in the LINUX environment.	
	the principles of Scripting Languages like Perl, TCL and Pythor	
3. To write	the scripts for automation using the languages like Perl, TCL and	d Python.
Expected Cour		
	e course the students will be able to	
	LINUX environment.	
-	the PERL scripts	
1	the TCL & TK scripts for automation	
1	the python scripts for automation	
J. write sc	ripts for a given EDA design automation	
Module:1 LI	NUX Basics	2 hours
	Linux, File System of Linux, General usage of Linux Kernel and	d Regio Commande
	d group, Permissions for file, directory and users, Searching a	
	ipping concepts.	a me and unectory,
	apping concepts.	
Module:2 PH	CRL Basics	5 hours
	ncepts of PERL - Scalar Data - Arrays and List Data - Control s	
	gular Expressions – Functions - Miscellaneous control structures	
		1 011114151
Module:3 Ac	lvanced Topics in PERL	4 hours
	s - File and Directory manipulation - Process Management - Pack	
Module:4 T	CL Basics	4 hours
	f TCL and Tk -Tcl Language syntax – Variables – Expressions –	
	Errors and exceptions - String manipulations.	
-		
Module:5 A	lvanced Topics in TCL	4 hours
	- Processes. Applications - Controlling Tools - Basics of Tk.	
Module:6 <b>P</b> y	thon Basics	4 hours
Introduction to	p Python - Using Python interpreter - Control flow Tools -	Data structures –
Modules		
Module:7 A	lvanced Topics in Python	4 hours
Input and Output	ut – Errors and Exceptions – Classes – Brief tour on standard libra	ary
Module:8 C	ontemporary issues:	2 hours
Total Lecture	nours:	30 hours
Reference Roo	ks	
Reference Boo		

1		0.1.0		
	Guido van Rossum Fred L. Drake, Jr., editor, "Python Tutorial Release 3.2.3", 2012.			
2.	Larry Wall, Tom Christiansen, John Orwant, "Programming PERL", Oreilly	Publications,		
	Fourth Edition, 2012.			
3.	John K. Ousterhout, Ken Jones, "Tcl and the Tk Toolkit", Pearson Educa	ation, Second		
	Edition, 2010.			
Mod	le of Evaluation: CAT / Assignment / Quiz / FAT / Project / Seminar			
List	of Challenging Experiments (Indicative)			
1.	Write a script to generate random test vectors for a given Verilog design.	3 hours		
2.	Write a script which reads a verilog design module and identifies whether it is	3 hours		
	a sequential or combinational design. Accordingly, the perl script should			
	generate the testbench file in verilog. Also, the input vectors from the			
	testbench should be in a randomized fashion.			
3.	Write a script that reads a set of log files from different simulation directories	2 hours		
	and generates a consolidated report in .xls format which should contain the			
	information of the test name, status and error messages. If the test is indicated			
	as successful in the log file, the status in the report should be as "TEST			
	PASSED" and if the test is unsuccessful, then the report should display the			
	status as "TEST FAILED".			
4.	Write a TCL Script which when executed should automatically compile your	3 hours		
	design modules and testbench modules and then perform the simulation. If the			
	simulation is successful, then the script should synthesize the design module.			
	The TCL script should also create a separate directory to dump the log files			
	and a separate directory to write the netlist file.			
5.	Write a script to perform netlist patching.	2 hours		
6.	Verification automation tool development using Perl/Python scripts	2 hours		
Tota	l Laboratory Hours	15 hours		
Mod	e of evaluation: Continuous Assessment Test -I (CAT-I), Continuous Assessment	ent Test –II		
(CA	T-II), Seminar / Challenging Assignments / Completion of MOOC / Innovative	ideas leading to		
	tions for industrial problems, Final Assessment Test (FAT).			
Reco	ommended by Board of Studies 05-03-2019			
App	roved by Academic Council No. 54 Date 14-03-2019			

Course code	Course Title	L T P J C
ECE 6024	VLSI Verification Methodologies	2 0 0 4 3
Pre-requisite	ECE5017 Digital Design with FPGA	Syllabus version
•		v. 1.0
Course Objective:		
1. To introduce vari	ous verification techniques.	
2. To write Testben	ch using System Verilog.	
3. To develop UVM	I test bench environment	
Expected Course (		
The students will be		
-	VLSI verification techniques.	
2. Define classes an	5	
	sing system verilog.	
	n environment using System Verilog.	
	A Verification environment.	
6. Create reusable v	erification environment using UVM.	
M. J. J. 1		4 1
	cation Techniques rification - Testing Vs Verification - Verification Tech	4 hours
	coverage – Functional coverage. Testbench – Linear Testb	
Testbench - Self-ch	ecking Testbench – Regression - RTL Formal Verification	
Module:2 Basic	OOP	3 hours
	Creating Object, object deallocation, copying objects, s	
variables, Inheritan		
	m Verilog – Data Types & Procedural statements	
	tem Verilog – Literal values-data Types – Arrays – Arra	
• • • • •	bedef – user defined structures – Enumerated types – a	-
	edural statements and control flow - Processes in System	m Verilog – Task and
functions – Routine	arguments – Returning from a routine	
Madulad Cana	ating Togth angle and Daging	2 h a
	cting Testbench and Design Stimulus timing, Module interactions, Connecting toge	3 hours
-	vironment – Generator, Transactor, Driver, Monitor, Che	-
sent-enceking test e	Trionment – Generator, Transactor, Driver, Monitor, Che	cker, Scoreboard
Module:5 Rando	mization, Assertion and Coverage	3 hours
	system Verilog, Constraints, Functional coverage, cross c	
Assertions		
L		
	rsal Verification Methodology	4 hours
Introduction to UV	M - Verification components - Transaction level modeling	2
Module:7 UVM	– Verification Environments	5 hours
	le verification components - Using Verification comp	
	n environment – Register classes.	Jonents – Developing
	renvironment register classes.	
Module:8 Cont	emporary issues:	2 hours
		2 110015

	Total Lecture hours:	30 hours
Ref	erence Books:	
1.	Vanessa R. Copper, "Getting started with UVM: A Beginner's Guide", Verilab Pu Edition, 2013.	ıblishing, First
2.	Ray Salmei, "The UVM Primer: A Step-by-Step Introduction to the Universal Methodology" Boston Light Press; First edition, 2013.	
3.	Christian B Spear, "System Verilog for Verification: A guide to learning the language features", Springer publications, Third Edition, 2012.	
4.	Janick Bergeron, "Writing Testbenches using System Verilog" Synopsys Publications, 2006.	Inc., Springer
Mo	de of Evaluation: CAT / Assignment / Quiz / FAT / Project / Seminar	
<b>Lis</b> 1.	t of Challenging Projects (Indicative) Develop a system Verilog testbench to verify your DUT by following the steps gives	
	<ul> <li>i) Write the following blocks in system Verilog to verify your design <ul> <li>a. Program Block</li> <li>b. Interface Block with clocking block and modport</li> <li>c. Top Level Harness file which has the instance of your DUT, test prointerface.</li> <li>ii) Develop the Generator, Transactor and Driver components for your DUT</li> <li>iii) Develop the self-checking feature by writing the receiver, monitor components for your DUT.</li> <li>iv) Simulate and verify the output.</li> </ul> </li> </ul>	
2.	Define a packet class to encapsulate the packet information and create random pa the generator then send, receive and check the correctness of the DUT using the for the given router IP. Follow the instructions given in the lab to complete the and verify the output for the good RTL code and the faulty code. Include co check the functional coverage is greater than 90%.	packet objects task. Simulate vergroups and
(CA	de of evaluation: Continuous Assessment Test –I (CAT-I), Continuous Assessmen AT-II), Seminar / Challenging Assignments / Completion of MOOC / Innovative identions for industrial problems, Final Assessment Test (FAT).	
Rec	commended by Board Of Studies 05-03-2019	
An	proved by Academic Council No. 54 Date 14-03-2019	

Course Code	Course title	L T P J C
ECE6025	LOW POWER IC DESIGN	2 0 0 4 3
Pre-requisite	ECE5015 - Digital IC Design	

## **Course Objective :**

The course is aimed to

- 1. Understand the concepts and techniques of Low power VLSI.
- 2. Develop a broad insight into the methods used to confront the low power issue from lower level (circuit level) to higher levels (system level) of abstraction.
- 3. develop a system with multiple supply and threshold voltages used for low power DSP applications.

#### **Expected Course Outcome :**

After completion of the course student will be able to:

- 1. Understand the factors affecting the power in VLSI circuits.
- 2. Apply algorithmic and architectural level power optimization methods.
- 3. Apply logic and circuit level power optimization techniques.
- 4. Apply register transfer level power optimization techniques.
- 5. Develop an optimum code to reduce the power in the software level.
- 6. Analyse and explore the usage of sleep transistors for low power.
- 7. Develop power efficient IPs.

#### **Introduction to Low Power Design Methods** Module:1

Motivation- Context and Objectives-Sources of Power dissipation in Ultra Deep Submicron CMOS Circuits - Static, Dynamic and Short circuit components Effects of scaling on power consumption-Low power design flow- Normalized Figure of Merit - PDP& EDP- Overview of power optimization at various levels.

#### Module:2 | Algorithmic and Architecture Level Optimization

Pipelining and Parallel Processing approaches for low power in DSP filter structures- Multiple supply voltage and Multiple threshold voltage designs for low power- Computer arithmetic techniques for low power- Optimal drivers of high speed low power- software level power optimization.

## Module:3 | Logic Level and Circuit Level Optimization

Theoretical background - Calculation of Steady state probability- Transition probability Conditional probability- Transition density- Estimation and optimization of Switching activity-Power cost computation model.

Transistor variable re-ordering for power reduction- Low power library cell design (GDI)-Estimation of glitching power- leakage power optimization-Subthreshold logic design.

#### Module:4 **Register Transfer Level Optimization**

Low power clock-Interconnect and layout designs- Low power memory design and low power SRAM architectures- Clock gating- Bus Encoding techniques-Deglitching for low power.

#### Module:5 Low Power Design of Sub-Modules **5hours** Circuit techniques for reducing power consumption in Adders- Multipliers. Synthesis of FSM for

4 hours

3 hours

**5hours** 

low power- Retiming sequential circuits for low power.

Module:6Sleep Transistor Design3hoursDesign metrics- switch efficiency- area efficiency- IR drop, normal Vs reverse body bias -Layout<br/>design of Area efficiency- Single row Vs double row- Inrush current and current latency.3hours

Module:7IP Design for Low Power3hoursArchitecture and partitioning for power gating- power controller design for the USB OTG- Issuesin designing portable power controllers- clocks and resets- Packaging IP for reuse with powerintent.

Mo	Module:8Contemporary issues:2 hours					
1010	uuleto	Total Lecture hours:	30hours			
Теу	kt Book(		0010015			
1.		Rabaey, MassoudPedram, Low power Design methodologies,SpringerU	S, First Edition,			
2.		k Roy, Sharat Prasad, Low Power CMOS VLSI circuit design, John V cond Edition, 2010.	Wiley and Sons			
Ref	ference ]	Books				
1.		s, Dimitrios, ChristrianPignet, Goutis, Costas, Designing CMOS circuits er US, FirstEdition, 2011.	for low power,			
2.	Gary K	.Yeap, Practical Low Power Digital VLSI Design, Springer US, First Ed	lition 2010.			
3.	AjitPal	, Low Power VLSI circuits and Systems, Springer India, First Edition, 2	.014.			
Mo	de of E	valuation:Continuous Assessment Test -I (CAT-I), Continuous Asses	ssment Test –II			
(CA	AT-II), S	eminar / Challenging Assignments / Completion of MOOC / Innovativ	ve ideas leading			
to s	olutions	for industrial problems, Final Assessment Test (FAT).	_			
Lis	t of Pro	jects (Indicative)				
	1. Desi	gn of Low Power, High Speed VLSI Adder and Multiplier Subsystems				
	2. Pow	er Gating Design solutions for Low Power				
	3. Circ	uit level power reduction using multi-V <sub>t</sub>				
	4. Non-conventional Low Power Circuits such as Energy Recovery Logic					
	5. Desi	gn of Low Power Clocking Solution for a Sequential System				
	6. Low	power SRAM and CAM design				
	7. Low	Power FFT Design for Wireless Communication Systems				
		Power Filter design for SDR systems.				
L						

Mode of Evaluation: Review I, II & III			
Recommended by Board of Studies	13-12-2015		
Approved by Academic Council	No. 40	18-03-2016	

<b>Course Code</b>	Course Title	L T P J C
ECE6026	MIXED SIGNAL IC DESIGN	2 0 0 4 3
Pre-requisite	ECE5016-Analog IC Design	
<b>Course Objecti</b>	ve:	
The course is air	ned to	
1. introduce	the design aspects of dynamic analog circuits and analog-digital inte	erface
electroni	cs in CMOS technology.	
2. Specify of	lesign implement ADC & DAC.	
<b>Expected Cour</b>	se Outcome :	
	course the student will be able to	
1. Understa	nd the theory of discrete-time signal processing and its implementation	on using
	chniques.	C
2. Realizing	s Sample and Hold Circuits using MOS by considering the non-ideality	ties.
3. Analyse	CMOS based Switched Capacitor Circuits.	
•	nding basics of Data Converters.	
5. Analyse	the architectures of ADCs and DAC.	
6. Understa	nd the oversampling converter architecture.	
7. Gain mix	ed-signal design experience using Cadence EDA tools.	
Module:1 Sa	npling	3hours
Introduction - s	ampling - Spectral properties of sampled signals - Oversampling – Ai	nti-alias filter
design. Time In	terleaved Sampling - Ping-pong Sampling System - Analysis of off	fset and gain
errors in Time In	terleaved Sample and Hold.	
Module:2 San	npling Circuits:	3 hours
Sampling circuit	ts- Distortion due to switch - Charge injection - Thermal noise in	sample and
holds - Botton	n plate sampling - Gate bootstrapped switch -Nakagome ch	narge pump
Characterizing S	ample and hold - Choice of input frequency.	
I	itched Capacitor Circuits:	4hours
Module:3   Sw	citor (SC) circuits- Parasitic Insensitive Switched Capacitor ampl	lifiers - Nor
	and (SC) chedits i didshie inscristive Switched Capacitor diffe	
Switched Capa		
Switched Capa idealities in SC	Amplifiers – Finite gain - DC offset - Gain Bandwidth Product. Full negative feedback in SC circuits.	
Switched Capa idealities in SC	Amplifiers – Finite gain - DC offset - Gain Bandwidth Product. Full	
Switched Capa idealities in SC SC circuits - DC	Amplifiers – Finite gain - DC offset - Gain Bandwidth Product. Full negative feedback in SC circuits.	y differentia
Switched Capa idealities in SC SC circuits - DC Module:4 A/I	<ul> <li>Amplifiers – Finite gain - DC offset - Gain Bandwidth Product. Full negative feedback in SC circuits.</li> <li>D and D/A Converters Fundamentals:</li> </ul>	y differential
Switched Capa idealities in SC SC circuits - DC Module:4 A/I Data converter	<ul> <li>Amplifiers – Finite gain - DC offset - Gain Bandwidth Product. Full negative feedback in SC circuits.</li> <li>D and D/A Converters Fundamentals:</li> <li>Fundamentals: Offset and gain Error - Linearity errors - Dynamic Characteric</li> </ul>	y differentia
Switched Capa idealities in SC SC circuits - DC Module:4 A/I Data converter	<ul> <li>Amplifiers – Finite gain - DC offset - Gain Bandwidth Product. Full negative feedback in SC circuits.</li> <li>D and D/A Converters Fundamentals:</li> </ul>	y differentia
Switched Capa idealities in SC SC circuits - DC Module:4 A/I Data converter SQNR - Quantiz	<ul> <li>Amplifiers – Finite gain - DC offset - Gain Bandwidth Product. Full negative feedback in SC circuits.</li> <li>D and D/A Converters Fundamentals:</li> <li>Fundamentals: Offset and gain Error - Linearity errors - Dynamic Characteric</li> </ul>	y differentia

Flash ADC - Regenerative latch - Preamp offset correction - Preamp Design - necessity of upfront sample and hold for good dynamic performance. Folding ADC - Multiple-Bit Pipeline ADCs and SAR ADC.

## Module:6 Digital to Analog Converter Architectures:

5hours

DAC spectra and pulse shapes - NRZ vs RZ DACs. DAC Architectures: Binary weighted - Thermometer DAC - Current steering DAC - Current cell design in current steering DAC - ChargeScaling DAC - Pipeline DAC.

		<b>Oversampling Converter:</b>			7hours
		Oversampling -Oversampl	0 1 0	ē	
		First and Second Order D			
		a Modulators - time-scaling			
		f Op-amp nonidealities - E	1 I	ties - finite gain b	oandwidth -
Eff	ect of Al	DC and DAC nonidealities - 1	Effect of Clock jitter.		
Mo	odule:8	Contemporary issues:			2hours
			Total	Lecture hours:	30hours
-			10tai	Lecture nours:	JUNUUTS
	xt Book(	/		1 4 11 .1 .	1 1'
1.		Ohnhauser, Analog-Digital			0
-		ction to Digital-Analog Conv	X _ V		
2.	David . 2012.	Johns and Ken Martin, Ana	log Integrated Circuit Desi	ign, John Wiley &	z Sons Inc.
Re	ference I	Books			
1.	Ahmed Edition	M.A.Ali, High Speed Dat	a Converters IET Materia	ls, Circuits & De	vices, First
2.		, 2010. n,R. Schreier and Gabor.C.Te	mes Understanding Delta	Sigma Data Cons	ortors
2.		ress, First Edition, 2017.	entes, Onderstanding Detta -	- Sigina Data Conv	verters,
		aluation: Continuous Assessi			
		eminar / Challenging Assignment	1	DC / Innovative ide	as leading
		for industrial problems, Fina	l Assessment Test (FAT).		
Ty	pical Pro				
		gn of Flash ADC			
		gn of High Speed Sample an	d Hold Amplifier.		
		gn of Charge Pump Circuit.			
		gn of Switched Capacitor Int	-		
		gn of Current – Steering DA	C		
N/	ode of Ev	aluation :Review I, II & III			
IVIC		led has Described Chardles	13-12-2015		
	comment	led by Board of Studies	15-12-2015		

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<b>Course Code</b>	Course Title	T P J C
ECE6027	RFIC DESIGN 2	2 0 0 4 3
<b>Pre-requisite</b>	ECE5016 - Analog IC Design	
<b>Course Objecti</b>	ves:	
The course is air	ned at	
1. To becom	ne familiarize with the design of integrated radio front-end circuits.	
<b>Expected Cours</b>	se Outcomes:	
At the end of the	course the student should be able to	
1. Understa	nd the concepts of RF IC Design.	
2. Understa	nd the High Frequency model of MOS and importance of Impedance	Matching.
3. Analyse	the various transceiver and radio architectures.	
4. Design L	ow Noise amplifiers and Mixers with specifications.	
5. Realize V	/COs and Frequency synthesizers and their applications to transceiver	design.
6. Classify	and comprehend the design of Power Amplifiers.	
7. Gain RF	C design experience in Cadence CAD tools.	
Module:1 Int	roduction to RF & Wireless Technology:	5hours
Complexity des	ign and applications - Choice of Technology - Basic concepts in	RF Design:
Nonlinearly - Ti	me Variance - Intersymbol Interference - random processes - Noise. I	Definitions of
	amic range -conversion Gain and Distortion.	
sensitivity ayin	and funge conversion can and Distortion.	
Module:2 Hig	h Frequency Model of RF Transistors and Matching Networks:	4hours
	iour at RF frequencies - Noise performance and limitation of devices	
	ks - transformers and baluns.	1
0		
Module:3 An	alog& Digital Modulation for RF Circuits:	4hours
	on coherent detection - Mobile RF Communication systems and basic	s of Multiple
Access techniq	ues - Receiver and Transmitter Architectures and Testing: H	leterodyne -
	ge-reject, Direct-IF and subsampled receivers - Direct Conversion a	
transmitters.		1
Module:4 Lov	w Noise Amplifiers and Mixers	4hours
	plifiers: Common Source LNA - Common Gate LNA -Cascode L	NA. Mixers:
	and Passive Mixers.	
Module:5 Vo	tage Controlled Oscillators and Frequency Synthesizers:	3hours
	sic topologies VCO and definition of phase noise. Noise-Pow	
	CO design - Quadrature and single-sideband generators - Radi	
Synthesizers: PL		requerey
Synthesizers. I L		
Modula:6 DE	Dowor Amplifiors:	Ahanna
Module:6 RF	Power Amplifiers:	4hours

Module:6RF Power Amplifiers:Class A, AB, B, C amplifiers - Class D, E, F amplifiers - RF Power amplifier design.

4hours

## Module:7 Radio architectures:

GSM radio architectures, CDMA, UMTS radio architectures.

Mo	odule:8 Contemporary issues:	2	hours			
	T	otal Lecture hours:	30hours			
Tex	xt Book(s)	ŀ				
1.	B.Razavi, RF Microelectronics, Pearson	Education Limited, Second Edition, 2013.				
2.		ated Circuits and Systems, Cambridge U	niversity			
	Press, First Edition, 2015.					
_	ference Books					
1.		nsceivers for Wireless Communications, S	springer,			
	2010					
2.	Bosco Leung, VLSI for Wireless Commu		<b>— — — —</b>			
		Test –I (CAT-I), Continuous Assessment				
		/ Completion of MOOC / Innovative ideas	leading			
	solutions for industrial problems, Final Ass	ssment Test (FAT).				
Lis	t of Projects(Indicative)					
	1. I-V Characterisation study of RF device/circuit					
	2. Design of Low Noise Amplifier					
	3. Design of Voltage Controlled Oscillators					
	4. Design of Power Amplifiers					
	5. Design and Implement- any one of the Receiver architecture					
Mo	Mode of Evaluation: Review I, II & III					
Rec	commended by Board of Studies 13-1	2-2015				
Ap	proved by Academic Council No.	40 18-03-2016				

Course Code	<b>Course Title</b>	T	1 P	-	C
ECE6028		2 0	0	) 4	3
<b>Pre-requisite</b>					
-	· · · · · · · · · · · · · · · · · · ·				
Course Objecti	ve :				
The course is	s aimed to				
1 Make str	ident to understand CMOS scaling				
	nd theory and operation of multigate MOSFET and analog design dig	tal c	irc	mits	
	Itigate devices aterials and their properties used for designing Microse			unus	
0	nd the concepts of Microsystem technologies used for realizing Micro			and	
actuators					
4. understan	nd the working principles of Interface Electronic Circuits for resistive	, capa	acit	tive	
and temp	perature sensors.				
Expected Cours					
	e course the students will be able to				
	ind the CMOS scaling				
	the need of novel MOSFET.				
	the physics of multigate MOS system anowire FETs.				
	igital and analog circuit using multigate devices.				
	and the physics of CNTFET				
	analytical model for novel FETs and validate them by numerical sim	ulati			
		uiaui	JHS	s	
p		ulatio	5115	5	
	CMOS Scaling Issues and Solutions			5 2hou	ırs
Module:1 (			2	2hou	
Module:1 C MOSFET scalin channel engined	CMOS Scaling Issues and Solutions ng, short channel effects, quantum effects, volume inversion, thre ering, source/drain engineering, high-k dielectric, strain engineer	shold	2 1 v	<b>2hou</b> olta	ge,
Module:1 C MOSFET scalin	CMOS Scaling Issues and Solutions ng, short channel effects, quantum effects, volume inversion, thre ering, source/drain engineering, high-k dielectric, strain engineer	shold	2 1 v	<b>2hou</b> olta	ge,
Module:1 C MOSFET scalin channel engined technology mob	CMOS Scaling Issues and Solutions ng, short channel effects, quantum effects, volume inversion, thre ering, source/drain engineering, high-k dielectric, strain enginee ility, gate stack.	shold	2 I v mu	<b>2hou</b> volta ultig	ge, ate
Module:1CMOSFET scaling channel engined technology mobilityModule:2	CMOS Scaling Issues and Solutions ng, short channel effects, quantum effects, volume inversion, thre ering, source/drain engineering, high-k dielectric, strain enginee ility, gate stack. ntroduction to Novel MOSFETs	shold ering,	2 1 v mu 2	2hou volta ultig 2hou	ge, ate
Module:1CMOSFET scalin channel enginer technology mobilityModule:2ISOI MOSFET,	CMOS Scaling Issues and Solutions ng, short channel effects, quantum effects, volume inversion, thre ering, source/drain engineering, high-k dielectric, strain enginee ility, gate stack. <b>ntroduction to Novel MOSFETs</b> multigate transistors, single gate, double gate, triple gate, surround	shold ering,	2 1 v mu 2	2hou volta ultig 2hou	ge, ate
Module:1CMOSFET scaling channel engined technology mobModule:2	CMOS Scaling Issues and Solutions ng, short channel effects, quantum effects, volume inversion, thre ering, source/drain engineering, high-k dielectric, strain enginee ility, gate stack. <b>ntroduction to Novel MOSFETs</b> multigate transistors, single gate, double gate, triple gate, surround	shold ering,	2 1 v mu 2	2hou volta ultig 2hou	ge, ate
Module:1CMOSFET scalin channel enginer technology mobilityModule:2ISOI MOSFET, Nanowire transis	CMOS Scaling Issues and Solutions ng, short channel effects, quantum effects, volume inversion, thre ering, source/drain engineering, high-k dielectric, strain enginee ility, gate stack. <b>ntroduction to Novel MOSFETs</b> multigate transistors, single gate, double gate, triple gate, surround	shold ering,	2 l v mu 2 e, S	2hou volta ultig 2hou	ge, ate Irs
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Module:1CMOSFET scaling channel enginer technology mobilityIModule:2ISOI MOSFET, Nanowire transisModule:3FMOS electrosta voltage effect, s tunnel current, tyModule:4N	CMOS Scaling Issues and Solutions ng, short channel effects, quantum effects, volume inversion, thre ering, source/drain engineering, high-k dielectric, strain engineering ility, gate stack. <b>ntroduction to Novel MOSFETs</b> multigate transistors, single gate, double gate, triple gate, surround stors <b>Physics of Multi-gate MOS System</b> tics, 1D, 2D MOS electrostatics, ultimate limits, double gate MOS emiconductor thickness effect, asymmetry effect, oxide thickness effect wo dimensional confinement, scattering	shold ering, l gate S sys fect	2 1 v mu 2 e, S 5 5 5 5 5 5 5 5 5 5 5 5 5	2hou volta ultig 2hou Silic 5hou n, g lectu	ge, ate
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Analog circuit design, trans-conductance, intrinsic gain, flicker noise, self-heating, band gap voltage reference, operational amplifier, comparator designs, mixed signal, successive approximation DAC, RF circuits

Module:7	Carbon Nanotube FET	4hours
CNT-FET, C	NT memories, CNT based switches, logic gates, CNT based RF device	es, CNT based
RTDs, CNTFI	ET based applications	

Mod	ule:8	Contemporary issues			2 hours	
			Total Lec	ture hours:	30hours	
Text	Text Book(s)					
1.	J P Col	inge, FINFETs and other Multi	-gate Transistors, Springer, C	Germany, 201	0.	
2.		rk, S.W. Hwang &Y.J.Park pre, 2012.	, Nanoelectronic Devices,	Pan Stanfo	ord Publisher,	
Refe	erence B	ooks				
1.	1. N. Collaert, CMOS Nanoelectronics: Innovative Devices, Architectures and Applications, Reprint Pan Stanford publisher, Singapore, 2012.					
2.	Niraj K. Jha, Deming Chen, Nanoelectronic Circuit Design, Springer London, First Edition, 2011.					
Mod	le of Ev	aluation:Continuous Assessme	nt Test -I (CAT-I), Contin	uous Assess	ment Test –II	
(CA	(CAT-II), Seminar / Challenging Assignments / Completion of MOOC / QUIZ, Final Assessment					
Test	(FAT).					
	of Proje					
		n and Extraction of DC and AC		th Source/Dra	ain Extension	
2. Performance Analysis of Double/Triple/Surround gate devices						
3	3. Analysis of Gate Work Function Engineering in Multi-gate Devices					
-	4. Single Event Upset/Soft Error Analysis in Multi-gate FETs					
5	5. Comparison of CMOS and Fin FET based SRAM					
6. Design of OTA and Comparator in Multi-gate Devices						
Mod	Mode of Evaluation: Review I, II & III					
Reco	ommende	ed by Board of Studies	13-12-2015			
Appr	roved by	Academic Council	No. 40	18-03-2016		